



One of the World's Largest
Manufacturers
of Discrete Semiconductors and Passive Components

Production Part Approval Process

The following PPAP documentation is assembled according to the AIAG, 4th Edition PPAP Manual and applicable customer requirements

IHLE2525xxERxxxM5A

Generic PPAP

Generic PPAP

8/31/2017

Production Part Approval Process

**The following PPAP documentation is assembled according to
AIAG, 4th Edition PPAP Manual and applicable customer requirements**

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Vishay / Dale Electronics

1505 East Hwy 50 Yankton, SD 57078, USA Phone (605) 665-9301 Fax (605) 668-4247

ONE OF THE WORLD'S LARGEST MANUFACTURERS OF DISCRETE SEMICONDUCTORS AND PASSIVE COMPONENTS

Production Part Approval Process

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**Note: Generic PPAPs do not include all sections shown in the Table of Contents.
Sections 4,5,6,7,8,12,&18 are only available upon request of a full Automotive PPAP.**

Production Part Approval Process

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Use the control buttons below to navigate through the PPAP sections.

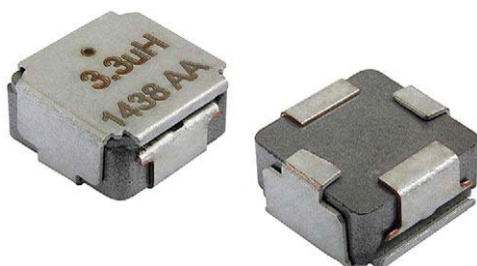
[Section 1. Design Records](#)

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ONE OF THE WORLD'S LARGEST MANUFACTURERS OF DISCRETE SEMICONDUCTORS AND PASSIVE COMPONENTS

IHLP® Automotive Inductors, High Temperature (155 °C) Series



DESIGN SUPPORT TOOLS click logo to get started



STANDARD ELECTRICAL SPECIFICATIONS

L ₀ INDUCTANCE ± 20 % AT 100 kHz, 0.25 V, 0 A (μH)	DCR TYP. 25 °C (mΩ)	DCR MAX. 25 °C (mΩ)	HEAT RATING CURRENT DC TYP. (A) ⁽¹⁾	SATURATION CURRENT DC TYP. (A) ⁽²⁾	SRF TYP. (MHz)
0.47	3.87	4.14	20.0	14.0	82.4
0.68	5.38	5.76	16.5	17.0	56.1
0.82	6.75	7.22	13.8	16.8	68.6
1.0	7.90	8.45	12.0	13.0	53.2
1.5	12.3	13.2	10.6	11.6	45.9
2.2	17.1	18.30	8.1	10.8	31.2
3.3	26.5	28.40	6.8	8.3	28.6
4.7	35.9	38.40	5.6	5.6	25.5
5.6	42.6	45.60	5.3	4.8	22.8
6.8	53.8	57.60	4.4	4.4	19.6
10	71.9	76.90	4.0	2.9	14.0
15	118.0	127.00	2.9	2.8	10.4
22	163.0	174.00	2.8	2.2	8.3

Notes

- All test data is referenced to 25 °C ambient
- Operating temperature range -55 °C to +155 °C
- The part temperature (ambient + temp. rise) should not exceed 125 °C under worst case operating conditions. Circuit design, component placement, PWB trace size and thickness, airflow and other cooling provisions all affect the part temperature. Part temperature should be verified in the end application
- Rated operating voltage (across inductor) = 50 V
- ⁽¹⁾ DC current (A) that will cause an approximate ΔT of 40 °C
- ⁽²⁾ DC current (A) that will cause L₀ to drop approximately 20 %

DESCRIPTION

IHLE-2525CD-5A	15 μH	± 20 %	ER	e3
MODEL	INDUCTANCE VALUE	INDUCTANCE TOLERANCE	PACKAGE CODE	JEDEC® LEAD (Pb)-FREE STANDARD

GLOBAL PART NUMBER

I	H	L	E	2	5	2	5	C	D	E	R	1	5	0	M	5	A
PRODUCT FAMILY				SIZE						PACKAGE CODE		INDUCTANCE VALUE			TOL.	SERIES	

FEATURES

- High temperature, up to 155 °C
- Integrated E-Shield for maximum EMI reduction ⁽¹⁾
- Excellent DC/DC energy storage up to 1 MHz to 2 MHz. Filter inductor applications up the SRF (see Standard Electrical Specifications table)
- Integrated e-field shield eliminates need for separate shielding
- 20 dB e-field reduction at 1 cm
 - Measured vertically from top center of device
- Lowest DCR/μH, in this package size
- Handles high transient current spikes without saturation
- Coplanarity of the 4 terminals ≤ 100 μm
- AEC-Q200 qualified
- Patent pending**
- Material categorization: for definitions of compliance please see www.vishay.com/doc?99912

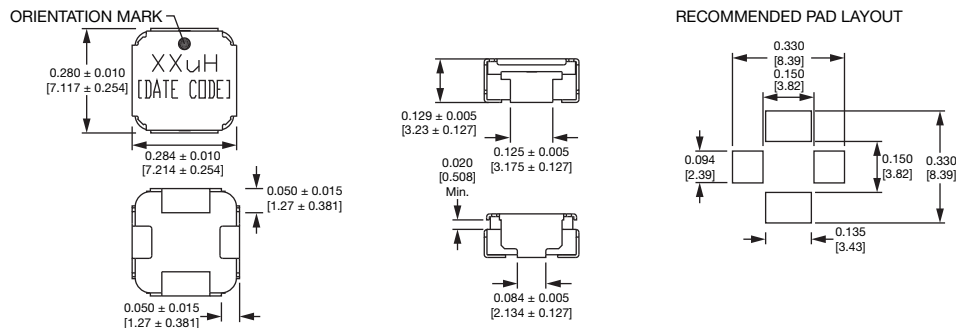
Note

- ⁽¹⁾ Maximum E-field reduction is realized with the IHLE shield is connected to ground

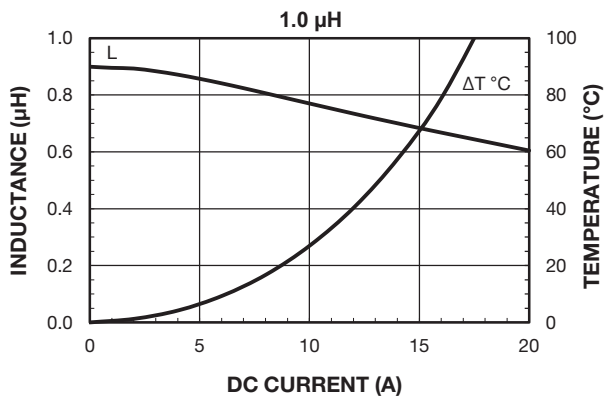
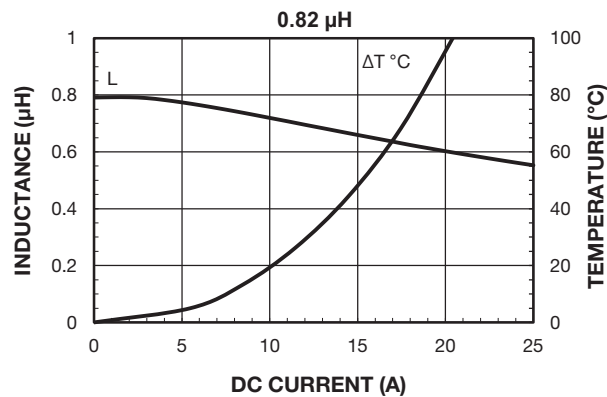
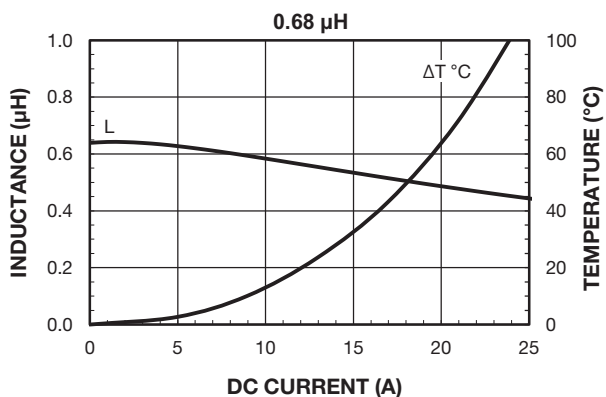
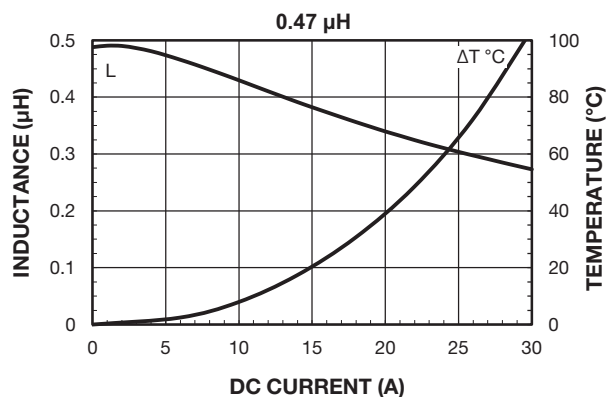
APPLICATIONS

- Engine and transmission control units
- Diesel injection drivers
- DC/DC converters for entertainment/navigation systems
- Noise suppression for motors
 - Windshield wipers
 - Power seats
 - Power mirrors
 - Heating and ventilation blower
 - HID lighting
- LED drivers



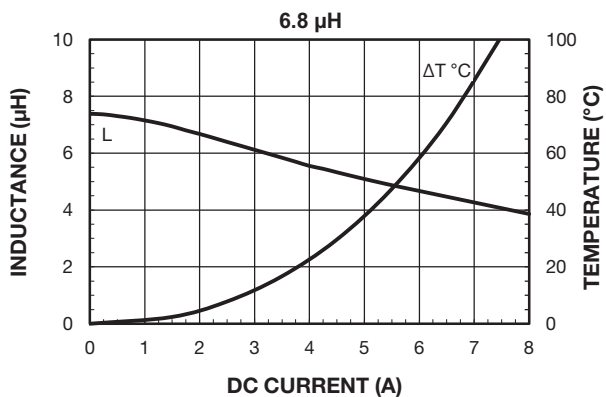
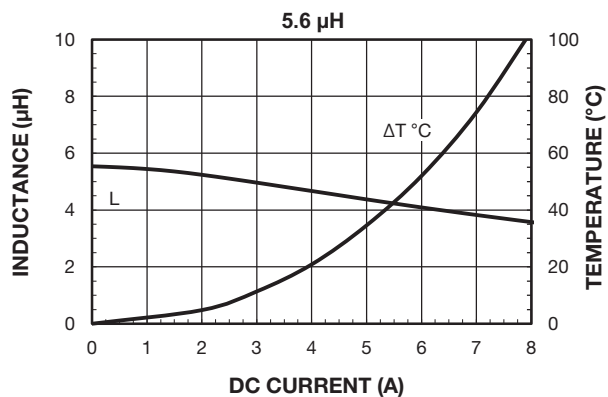
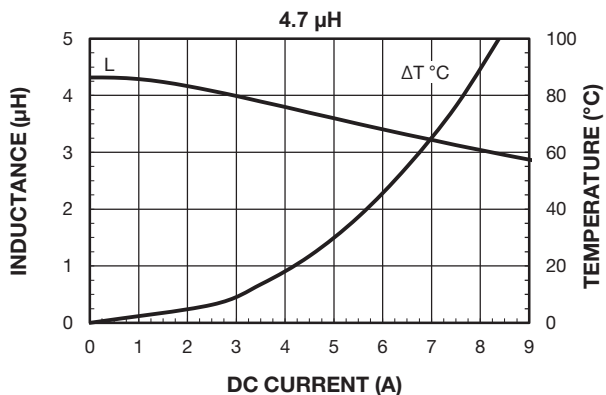
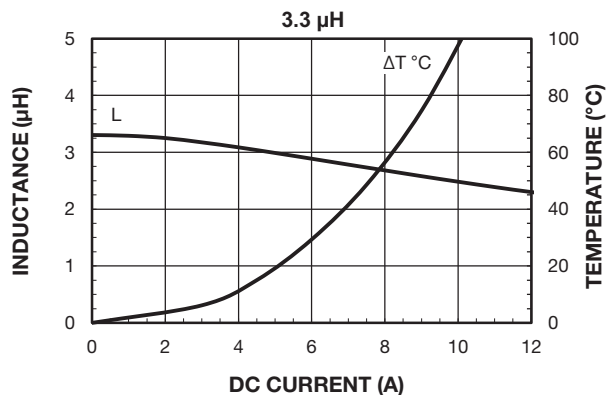
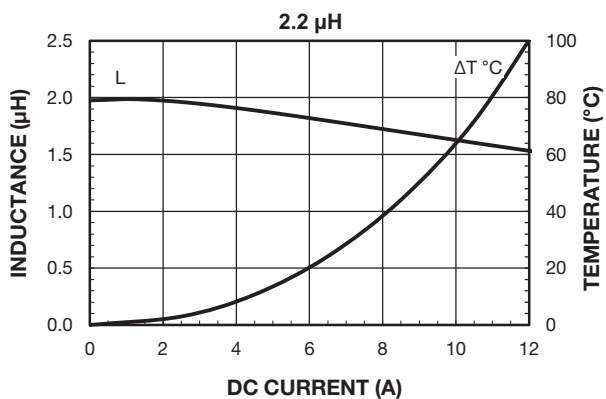
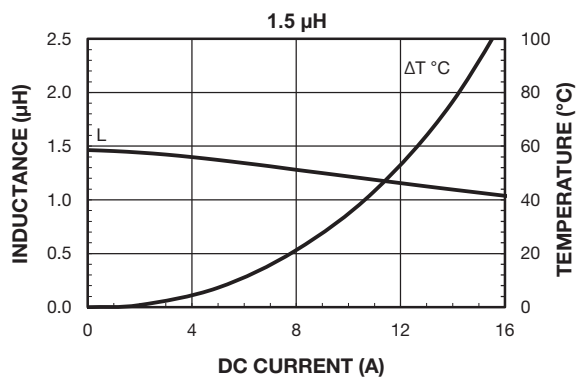
DIMENSIONS in inches [millimeters]

Notes

- Dot indicate the coil pin
- Coplanarity of 4 terminals: 0.004" [0.10]

PERFORMANCE GRAPHS


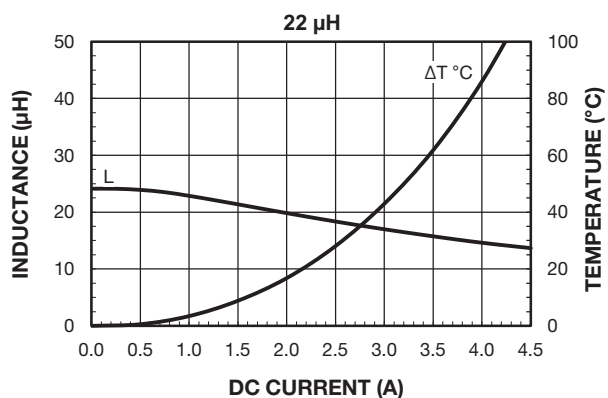
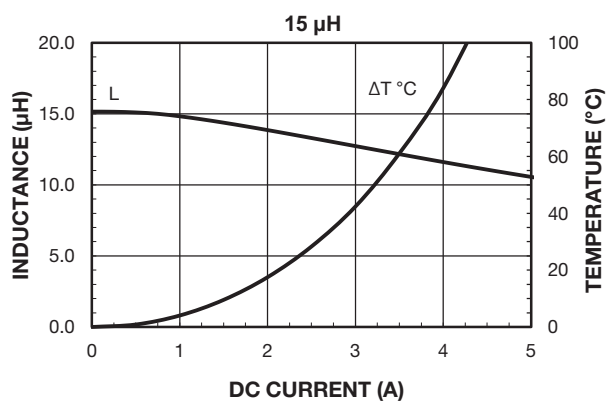
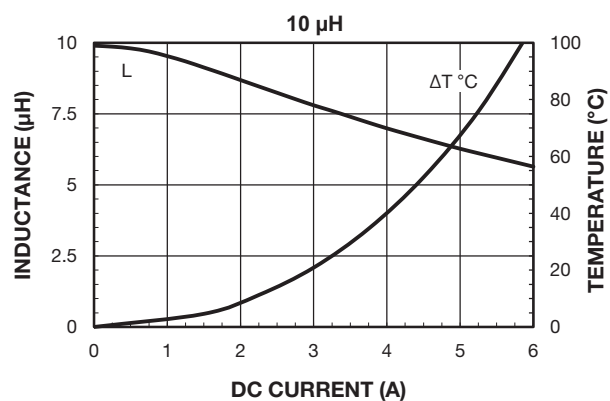


PERFORMANCE GRAPHS



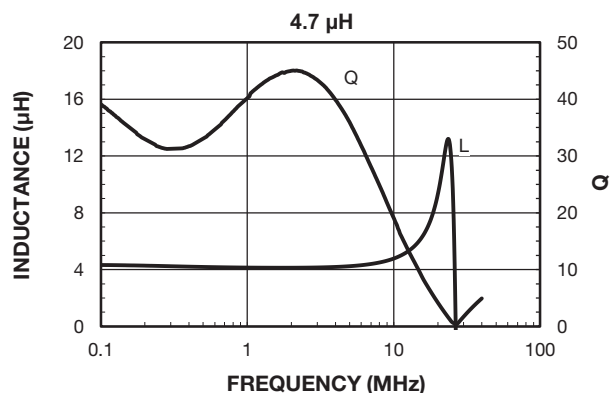
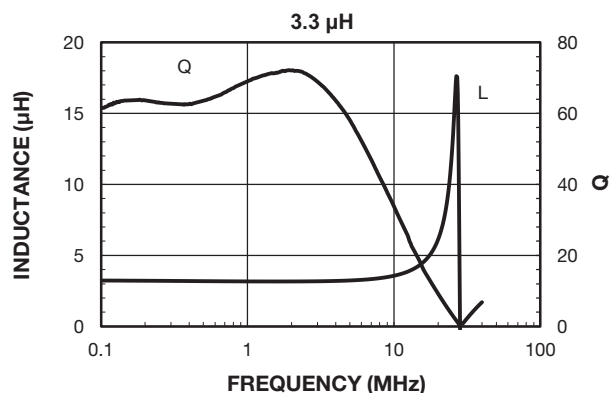
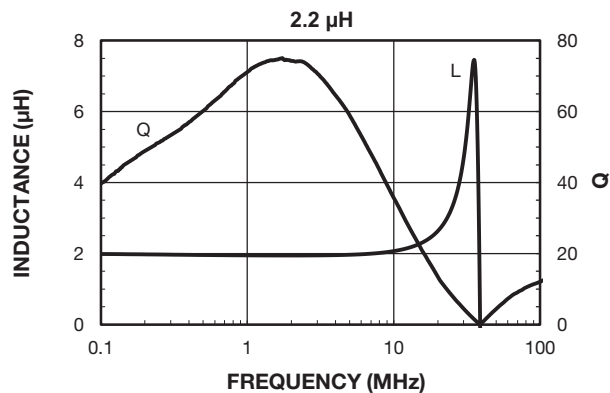
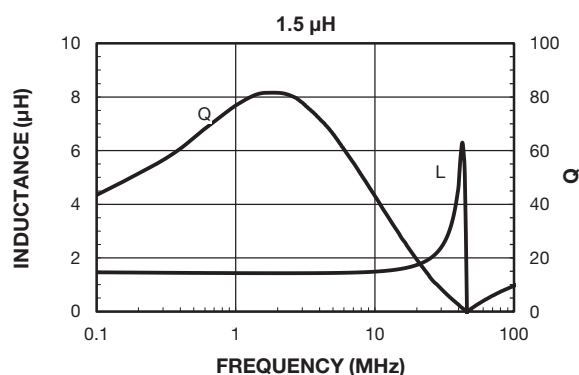
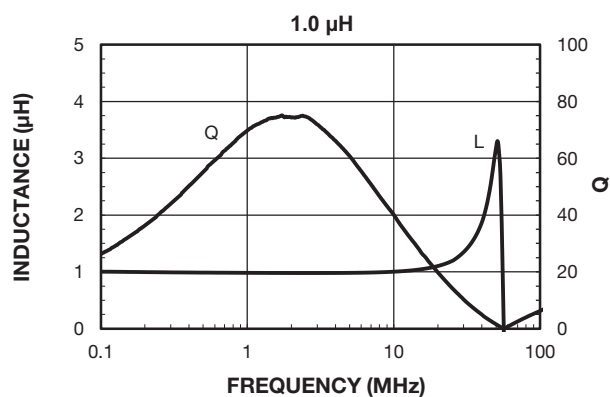
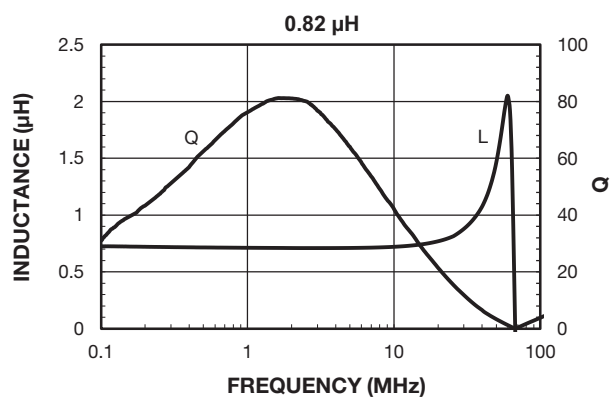
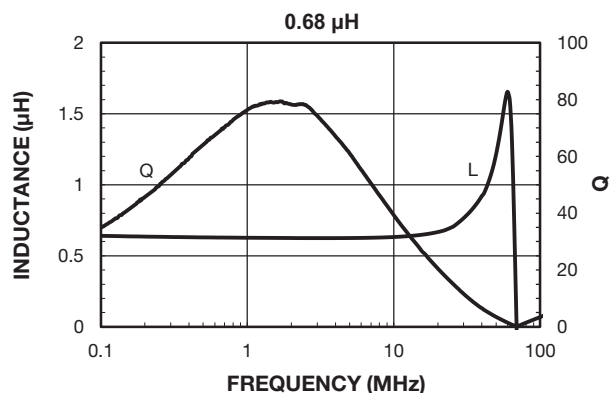
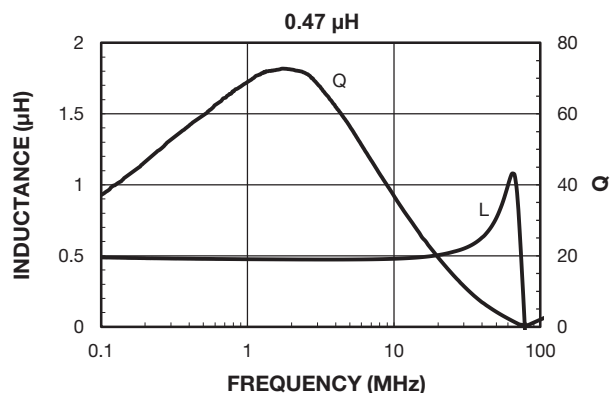


PERFORMANCE GRAPHS



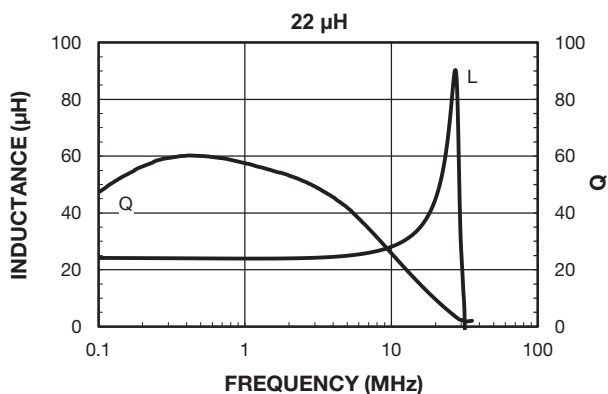
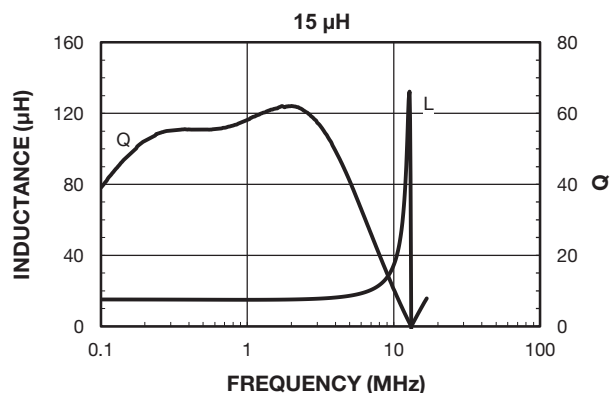
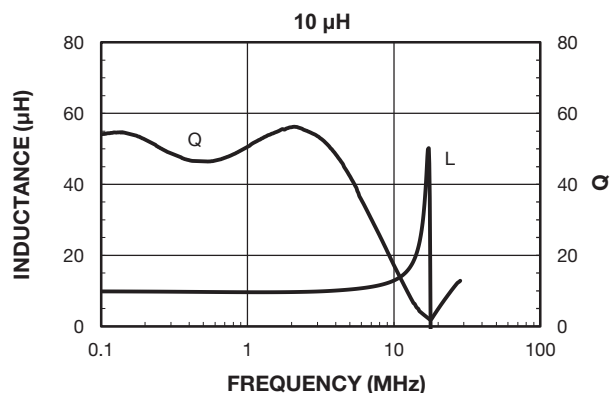
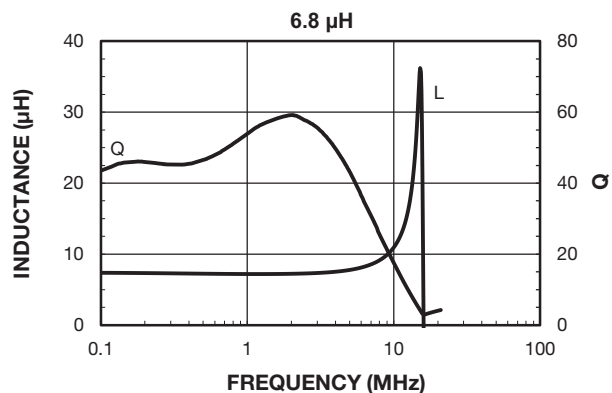
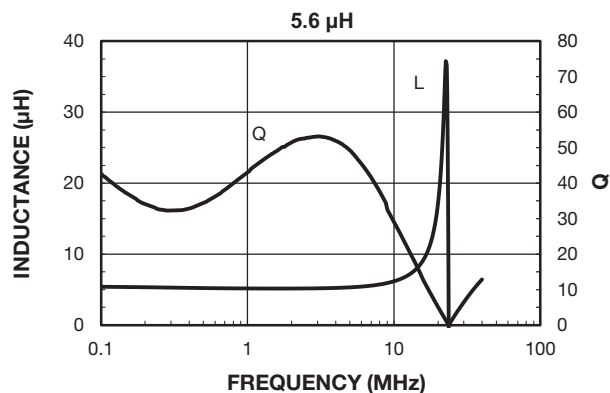


PERFORMANCE GRAPHS: INDUCTANCE AND Q VS. FREQUENCY



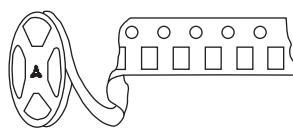


PERFORMANCE GRAPHS: INDUCTANCE AND Q VS. FREQUENCY

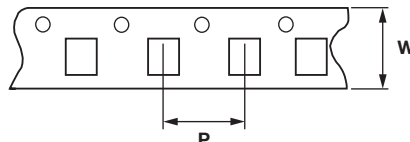


SMD Magnetics Packaging Methods

TAPE AND REEL in inches [millimeters] - Meets EIA RS-481 tape and reel packaging standard



User Direction of Feed



Carrier Dimensions

MODEL	PACKAGE CODE			REEL SIZE	CARRIER TAPE WIDTH (W)	COMPONENT PITCH (P)	UNITS/ REEL	PACKAGE CODE			UNITS/ BULK
	PREVIOUS CODE	GLOBAL CODE LEAD (Pb)- BEARING	GLOBAL CODE LEAD (Pb)-FREE					PREVIOUS CODE	GLOBAL CODE LEAD (Pb)- BEARING	GLOBAL CODE LEAD (Pb)-FREE	
IHLP-1212ABER	-	-	ER	13	0.472 [12.0]	0.315 [8.0]	3000	-	-	-	-
IHLP-1212ABEV	-	-	ER	13	0.472 [12.0]	0.315 [8.0]	4000	-	-	-	-
IHLP-1212AEER	-	-	ER	13	0.472 [12.0]	0.315 [8.0]	3000	-	-	-	-
IHLP-1212BZER	-	-	ER	13	0.472 [12.0]	0.315 [8.0]	3000	-	-	-	-
IHLP-1212BZEV	-	-	ER	13	0.472 [12.0]	0.315 [8.0]	4000	-	-	-	-
IHLP-1616AB	-	-	ER	13	0.472 [12.0]	0.315 [8.0]	4000	-	-	EB	100
IHLP-1616BZ	-	-	ER	13	0.472 [12.0]	0.315 [8.0]	4000	-	-	EB	100
IHLP-2020AB	-	-	ER	13	0.472 [12.0]	0.315 [8.0]	4000	-	-	EB	100
IHLP-2020BZ	-	-	ER	13	0.472 [12.0]	0.315 [8.0]	2000	-	-	EB	100
IHLP-2020CZ	-	-	ER	13	0.472 [12.0]	0.315 [8.0]	2000	-	-	EB	100
IHLP-2525AH	-	-	ER	13	0.630 [16.0]	0.315 [8.0]	2000	-	-	EB	100
IHLP-2525BD	-	-	ER	13	0.630 [16.0]	0.315 [8.0]	2000	-	-	EB	100
IHLP-2525CZ	-	-	ER	13	0.630 [16.0]	0.315 [8.0]	2000	-	-	EB	100
IHLP-2525EZ	-	-	ER	13	0.630 [16.0]	0.472 [12.0]	500	-	-	EB	100
IHLP-3232CZ	-	-	ER	13	0.630 [16.0]	0.472 [12.0]	1000	-	-	EB	100
IHLP-3232DZ	-	-	ER	13	0.630 [16.0]	0.472 [12.0]	500	-	-	EB	100
IHLP-4040DZ	-	-	ER	13	0.945 [24.0]	0.630 [16.0]	500	-	-	EB	100
IHLP-5050CE	-	-	ER	13	0.945 [24.0]	0.630 [16.0]	500	-	-	EB	100
IHLP-5050EZ	-	-	ER	13	0.945 [24.0]	0.630 [16.0]	250	-	-	EB	100
IHLP-5050FD	-	-	ER	13	0.945 [24.0]	0.630 [16.0]	250	-	-	EB	100
IHLP-6767DZ	-	-	ER	13	0.945 [24.0]	0.945 [24.0]	250	-	-	EB	100
IHLP-6767GZ	-	-	ER	13	0.945 [24.0]	0.945 [24.0]	200	-	-	EB	100
IHLP-8787MZ	-	-	ER	13	1.73 [44.0]	1.26 [32.0]	100	-	-	-	-
IHCL-4040DZ	-	-	ER	13	0.945 [24.0]	0.630 [16.0]	500	-	-	EB	100
IHLD-4032KB	-	-	ER	13	0.945 [24.0]	0.630 [16.0]	250	-	-	EB	100
IHLD-3232HB	-	-	ER	13	0.945 [24.0]	0.630 [16.0]	250	-	-	EB	100
IHLE-2525CD	-	-	ER	13	0.630 [16.0]	0.315 [8.0]	2000	-	-	EB	100
IHLE-3232DD	-	-	ER	13	0.630 [16.0]	0.472 [12.0]	500	-	-	EB	100
IHLE-4040DD	-	-	ER	13	0.945 [24.0]	0.630 [16.0]	500	-	-	EB	100
IHLR-4040DZ	-	-	ER	13	0.945 [24.0]	0.630 [16.0]	500	-	-	EB	100
IHLM-2525CZ	-	-	ER	13	0.630 [16.0]	0.315 [8.0]	2000	-	-	EB	100
IHLW-4040CF	-	-	ER	13	0.945 [24.0]	0.630 [16.0]	500	-	-	EB	100
IHLW-5050CE	-	-	ER	13	0.945 [24.0]	0.630 [16.0]	500	-	-	EB	100
IFLP-4040DZ	-	-	ER	13	0.945 [24.0]	0.630 [16.0]	500	-	-	EB	100
IFLR-2727EZ	-	-	ER	13	0.630 [16.0]	0.630 [16.0]	1000	-	-	-	-
IFLR-4027EZ	-	-	ER	13	0.945 [24.0]	0.630 [16.0]	1000	-	-	-	-
IFLR-4031GC	-	-	ER	13	0.945 [24.0]	0.472 [12.0]	500	-	-	EB	100
IFLR-5151HZ	-	-	ER	13	0.945 [24.0]	0.630 [16.0]	450	-	-	EB	100

**TAPE AND REEL** in inches [millimeters] - Meets EIA RS-481 tape and reel packaging standard

MODEL	PACKAGE CODE			REEL SIZE	CARRIER TAPE WIDTH (W)	COMPONENT PITCH (P)	UNITS/ REEL	PACKAGE CODE			UNITS/ BULK
	PREVIOUS CODE	GLOBAL CODE LEAD (Pb)- BEARING	GLOBAL CODE LEAD (Pb)-FREE					PREVIOUS CODE	GLOBAL CODE LEAD (Pb)- BEARING	GLOBAL CODE LEAD (Pb)-FREE	
IFSC-0806AZ	-	-	ER	7	0.315 [8.0]	0.157 [4.0]	2000	-	-	-	-
IFSC-1008AB	-	-	ER	7	0.315 [8.0]	0.157 [4.0]	2000	-	-	-	-
IFSC-1111AZ	-	-	ER	7	0.315 [8.0]	0.157 [4.0]	2000	-	-	-	-
IFSC-1111AB	-	-	ER	7	0.315 [8.0]	0.157 [4.0]	2000	-	-	-	-
IFSC-1515AH	-	-	ER	13	0.472 [12.0]	0.315 [8.0]	2000	-	-	-	-
IHHP-0806AZ-01	-	-	ER	7	0.315 [8.0]	0.157 [4.0]	2000	-	-	-	-
IHHP-0806AB-01	-	-	ER	7	0.315 [8.0]	0.157 [4.0]	2000	-	-	-	-
IHHP-1008AZ-01	-	-	ER	7	0.315 [8.0]	0.157 [4.0]	3000	-	-	-	-
IHHP-1008AB-01	-	-	ER	7	0.315 [8.0]	0.157 [4.0]	3000	-	-	-	-
IHHP-1212ZH-01	-	-	ER	7	0.315 [8.0]	0.157 [4.0]	3000	-	-	-	-
IHHP-1212AZ-01	-	-	ER	7	0.315 [8.0]	0.157 [4.0]	3000	-	-	-	-
IHSM-3825	RC2	RE	ER	13	0.945 [24.0]	0.472 [12.0]	750	P09	PJ	EB	100
IHSM-4825	RC2	RE	ER	13	0.945 [24.0]	0.472 [12.0]	750	P09	PJ	EB	100
IHSM-5832	RC3	RF	ER	13	1.26 [32.0]	0.472 [12.0]	500	P09	PJ	EB	100
IHSM-7832	RC4	RG	ER	13	1.73 [44.0]	0.472 [12.0]	500	P09	PJ	EB	100
IDC-2512	-	-	ER	13	0.630 [16.0]	0.315 [8.0]	2000	-	-	-	-
IDC-5020	-	-	ER	13	0.630 [16.0]	0.472 [12.0]	500	-	-	-	-
IDC-7328	-	-	ER	13	0.945 [24.0]	0.945 [24.0]	250	-	-	-	-
IDCS-2512	-	-	ER	13	0.630 [16.0]	0.315 [8.0]	2000	-	-	-	-
IDCS-5020	-	-	ER	13	0.630 [16.0]	0.472 [12.0]	500	-	-	-	-
IDCS-7328	-	-	ER	13	0.945 [24.0]	0.945 [24.0]	250	-	-	-	-
IDCP-1813	-	-	ER	13	0.472 [12.0]	0.315 [8.0]	2000	-	-	-	-
IDCP-2218	-	-	ER	13	0.472 [12.0]	0.315 [8.0]	1500	-	-	-	-
IDCP-3114	-	-	ER	13	0.630 [16.0]	0.472 [12.0]	1000	-	-	-	-
IDCP-3020	-	-	ER	13	0.630 [16.0]	0.472 [12.0]	1000	-	-	-	-
IDCP-3722	-	-	ER	13	0.945 [24.0]	0.472 [12.0]	500	-	-	-	-
IDCP-3916	-	-	ER	13	0.945 [24.0]	0.472 [12.0]	500	-	-	-	-
IFCB-0402	-	-	ER	7	0.315 [8.0]	0.079 [2.0]	10 000	-	-	-	-
ILC-0402	-	-	ER	7	0.315 [8.0]	0.079 [2.0]	10 000	-	-	-	-
ILC-0603	-	-	ER	7	0.315 [8.0]	0.157 [4.0]	4000	-	-	-	-
ILC-0805	-	-	ER	7	0.315 [8.0]	0.157 [4.0]	4000	-	-	-	-
IMC-0402	-	-	ER	7	0.315 [8.0]	0.079 [2.0]	10 000	-	-	-	-
IMC-0402-01	-	-	ER	7	0.315 [8.0]	0.079 [2.0]	10 000	-	-	-	-
IMC-0603	-	-	ER	7	0.315 [8.0]	0.157 [4.0]	4000	-	-	-	-
IMC-0603-01	-	-	ER	7	0.315 [8.0]	0.079 [2.0]	3000	-	-	-	-
IMC-0805-01	-	-	ER	7	0.315 [8.0]	0.157 [4.0]	2000	-	-	-	-
IMC-1008	-	-	ER	7	0.315 [8.0]	0.157 [4.0]	2000	-	-	-	-
IMC-1210	R98/RB3 R99/RB4	SY/AN SZ/R9	ER/ET ES/EU	7	0.315 [8.0]	0.157 [4.0]	2000	B13	BN	EB	500
				13	0.315 [8.0]	0.157 [4.0]	7500				
IMC-1210-100	R98/RB3 R99/RB4	SY/AN SZ/R9	ER/ET ES/EU	7	0.315 [8.0]	0.157 [4.0]	2000	B13	BN	EB	500
				13	0.315 [8.0]	0.157 [4.0]	7500				
IMC-1812	R73/R92 R13/R91	RV/RX RQ/RW	ER/ET ES/EU	7	0.472 [12.0]	0.315 [8.0]	500	B13	BN	EB	500
				13	0.472 [12.0]	0.315 [8.0]	2000				
IMCH-1812	-	-	ER	7	0.472 [12.0]	0.315 [8.0]	500	-	-	-	-
IMC-2220	-	-	ER	13	0.630 [16.0]	0.472 [12.0]	1000	-	-	-	-

IHLP PACKAGING

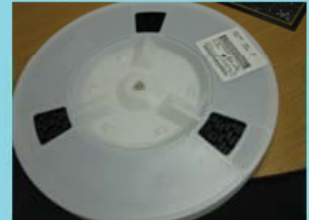
COMPONENT PHOTO



POCKET TAPE PHOTO



REEL PHOTO



CONTAINER PHOTO

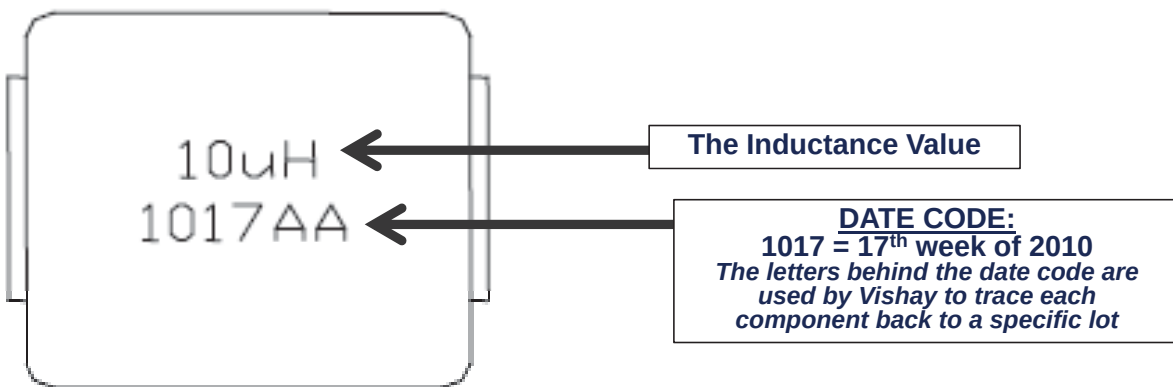


UNIT LOAD PHOTO





IHLP COMPONENT PRINT





Production Part Approval Process

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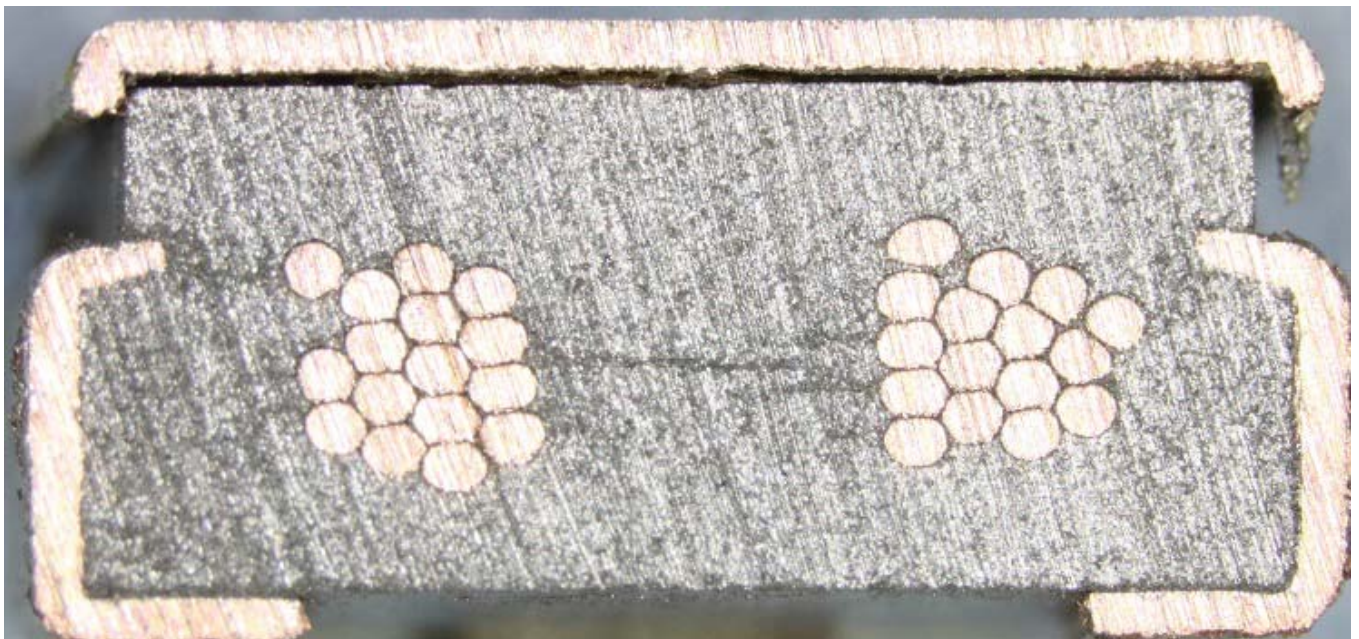
Terminal Plating Info

Part Number (CUSTOMER)	Part Number (Vishay)	Layer structure with base and coating material used:	Layer thickness and tolerances of the coatings (base material, intermediate layer, final finish)	Kind of Coating or technology (e.g. galvanized, chemically hot tin- plated,..)
Generic PPAP	IHLE2525xxERxxxM5A	Cu - Base Material Ni- Intermediate Layer Sn- Finish Layer	Cu: 0.203 +/- .0254mm Ni: 1.27um to 3.175um Sn: 4.57um to 6.35 um	Electroplated

Production Part Approval Process

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Cross Sectional Picture IHLE2525CDER6R8M5A





Production Part Approval Process

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Example Photos of IHLP Welds

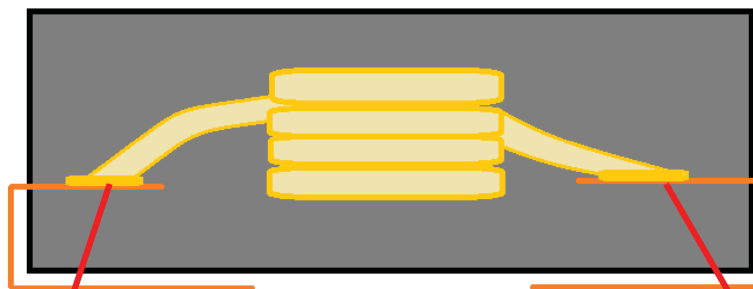




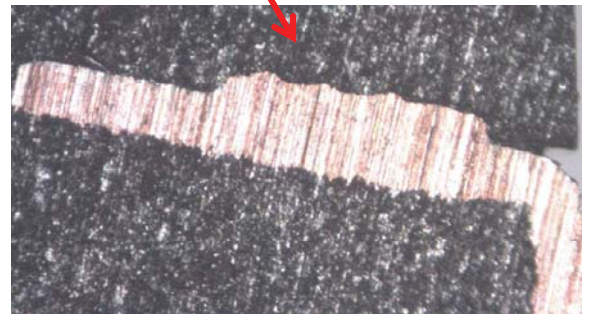
Production Part Approval Process

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Cross sectional Photos of IHLP Welds



Inter-Metallic
bonding
between the
wire and
Leadframe



Production Part Approval Process

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Use the control buttons below to navigate through the PPAP sections.

Section 2: Engineering Change Documents

There are no applicable Engineering Change Documents for this part number.

Vishay / Dale Electronics

1505 East Hwy 50 Yankton, SD 57078, USA Phone (605) 665-9301 Fax (605) 668-4247

ONE OF THE WORLD'S LARGEST MANUFACTURERS OF DISCRETE SEMICONDUCTORS AND PASSIVE COMPONENTS

Production Part Approval Process

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Use the control buttons below to navigate through the PPAP sections.

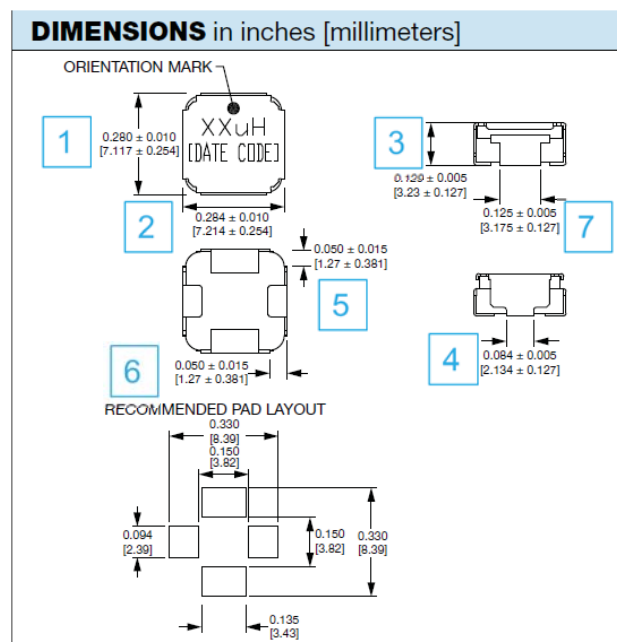
Section 3: Customer Engineering Approval

Customer Engineering Approval does not apply for this part number

Production Part Approval Process

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requirements

Dimensional Analysis IHLE2525CD



Production Part Approval Process

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Dimensional Analysis IHLE 2525CD

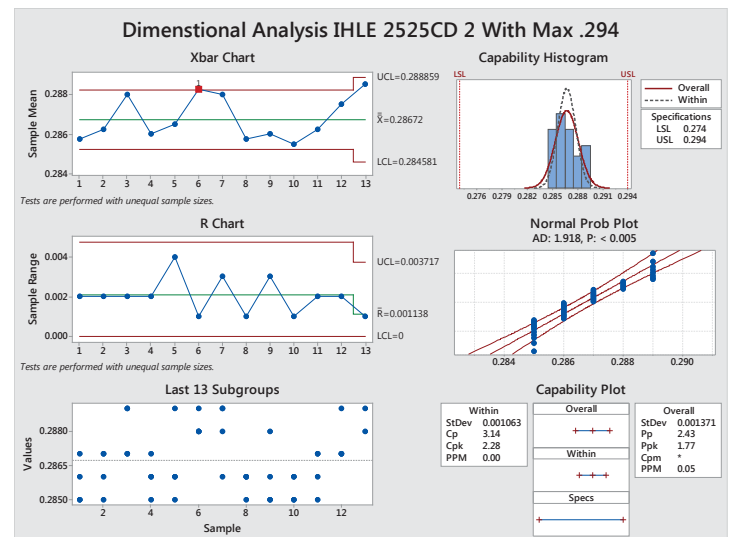
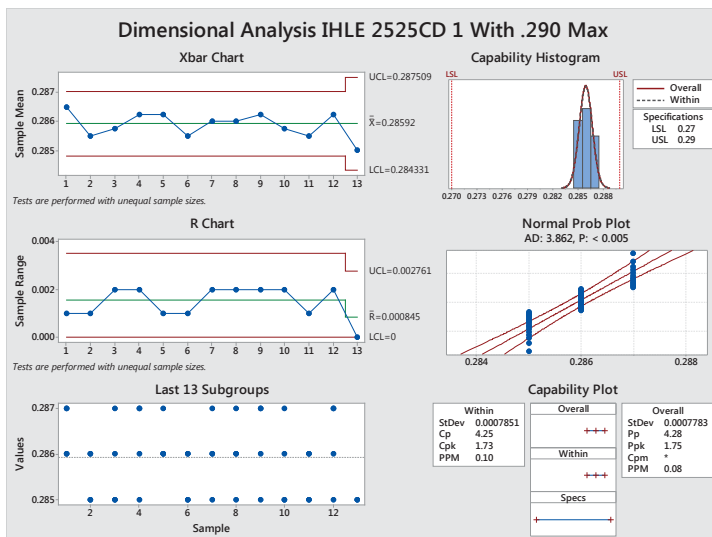
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1	0.287	0.285	0.129	0.086	0.048	0.050	0.125
2	0.286	0.285	0.130	0.086	0.048	0.051	0.125
3	0.287	0.287	0.130	0.086	0.049	0.045	0.125
4	0.286	0.286	0.129	0.086	0.048	0.047	0.126
5	0.285	0.287	0.130	0.086	0.049	0.046	0.125
6	0.286	0.285	0.131	0.086	0.050	0.047	0.125
7	0.285	0.287	0.131	0.086	0.048	0.047	0.125
8	0.286	0.286	0.129	0.086	0.047	0.050	0.125
9	0.286	0.287	0.130	0.086	0.049	0.047	0.125
10	0.285	0.289	0.130	0.086	0.048	0.049	0.125
11	0.285	0.289	0.129	0.086	0.049	0.050	0.125
12	0.287	0.287	0.129	0.086	0.048	0.048	0.125
13	0.286	0.286	0.131	0.086	0.049	0.048	0.125
14	0.287	0.287	0.131	0.086	0.050	0.047	0.125
15	0.285	0.286	0.131	0.086	0.049	0.047	0.125
16	0.287	0.285	0.130	0.086	0.047	0.046	0.125
17	0.286	0.286	0.129	0.086	0.048	0.050	0.125
18	0.287	0.285	0.129	0.086	0.049	0.046	0.125
19	0.286	0.286	0.129	0.086	0.050	0.047	0.125
20	0.286	0.289	0.130	0.086	0.048	0.049	0.125
21	0.286	0.288	0.130	0.086	0.045	0.047	0.125
22	0.285	0.288	0.131	0.086	0.045	0.044	0.125
23	0.286	0.289	0.129	0.087	0.050	0.049	0.125
24	0.285	0.288	0.131	0.086	0.048	0.045	0.125
25	0.286	0.289	0.130	0.086	0.045	0.045	0.125

Sample Number	1	2	3	4	5	6	7
	.290 max	.294 max	.134 max	.089 max	.065 max	.065 max	.130 max
26	0.286	0.289	0.131	0.086	0.050	0.048	0.125
27	0.287	0.288	0.129	0.086	0.051	0.048	0.126
28	0.285	0.286	0.129	0.087	0.045	0.049	0.125
29	0.287	0.286	0.131	0.086	0.047	0.048	0.126
30	0.286	0.286	0.130	0.086	0.046	0.049	0.125
31	0.286	0.285	0.131	0.086	0.047	0.050	0.125
32	0.285	0.286	0.131	0.086	0.047	0.048	0.125
33	0.287	0.285	0.130	0.086	0.050	0.047	0.125
34	0.285	0.288	0.129	0.086	0.047	0.049	0.125
35	0.287	0.286	0.130	0.086	0.049	0.048	0.125
36	0.286	0.285	0.130	0.086	0.050	0.049	0.125
37	0.285	0.286	0.131	0.086	0.048	0.048	0.125
38	0.287	0.286	0.131	0.086	0.048	0.049	0.125
39	0.286	0.285	0.130	0.086	0.047	0.050	0.125
40	0.285	0.285	0.130	0.086	0.047	0.049	0.125
41	0.285	0.287	0.131	0.086	0.046	0.047	0.125
42	0.286	0.286	0.131	0.086	0.050	0.048	0.125
43	0.285	0.287	0.129	0.086	0.046	0.049	0.125
44	0.286	0.285	0.129	0.086	0.047	0.050	0.125
45	0.287	0.287	0.131	0.086	0.049	0.048	0.125
46	0.287	0.289	0.129	0.086	0.047	0.045	0.125
47	0.285	0.287	0.130	0.086	0.044	0.045	0.125
48	0.286	0.287	0.129	0.086	0.049	0.050	0.125
49	0.285	0.289	0.129	0.086	0.045	0.048	0.125
50	0.285	0.288	0.130	0.086	0.045	0.045	0.125

Production Part Approval Process

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Dimensional Analysis IHLE 2525CD

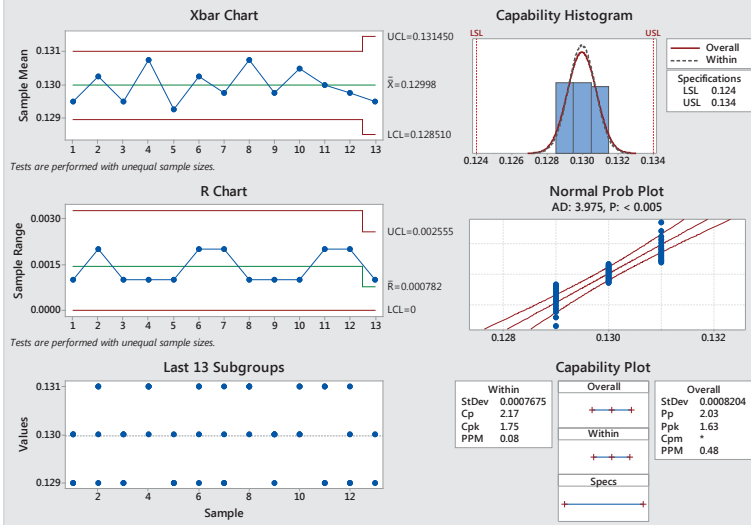


Production Part Approval Process

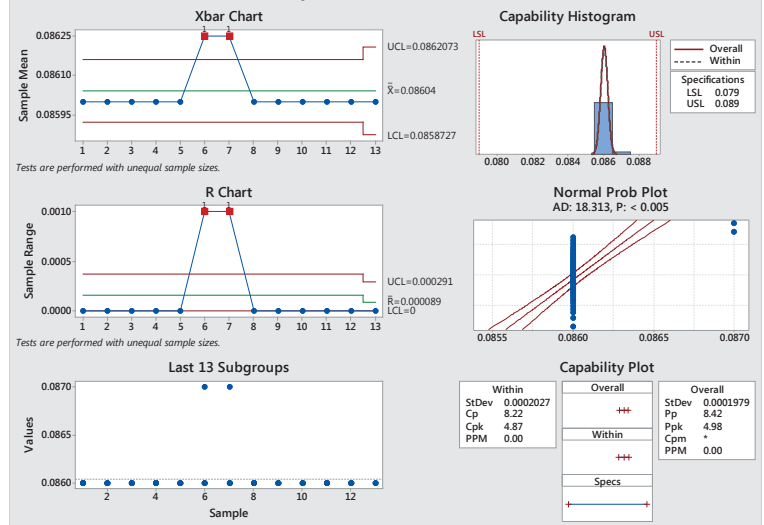
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Dimensional Analysis IHLE 2525CD

Dimensional Analysis IHLE 2525CD 3 With .134 Max



Dimensional Analysis IHLE 2525CD 4 With .089 Max

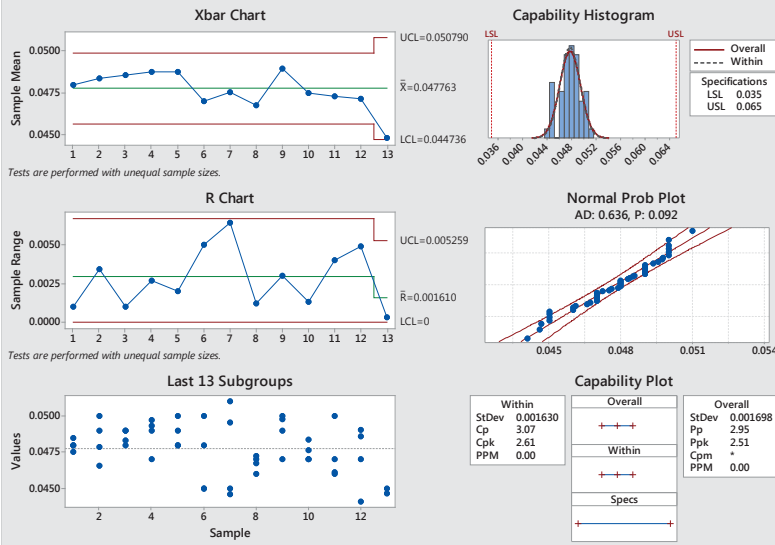


Production Part Approval Process

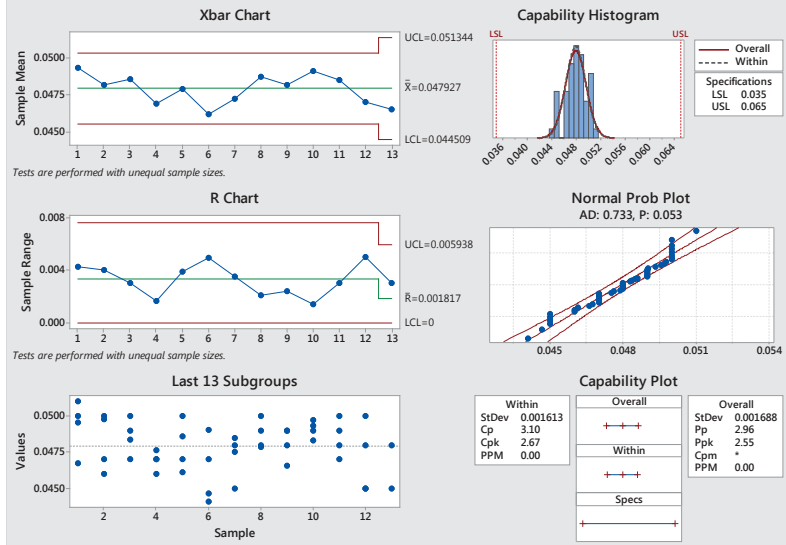
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Dimensional Analysis IHLE 2525CD

Dimensional Analysis IHLE 2525CD 5 With .065 Max



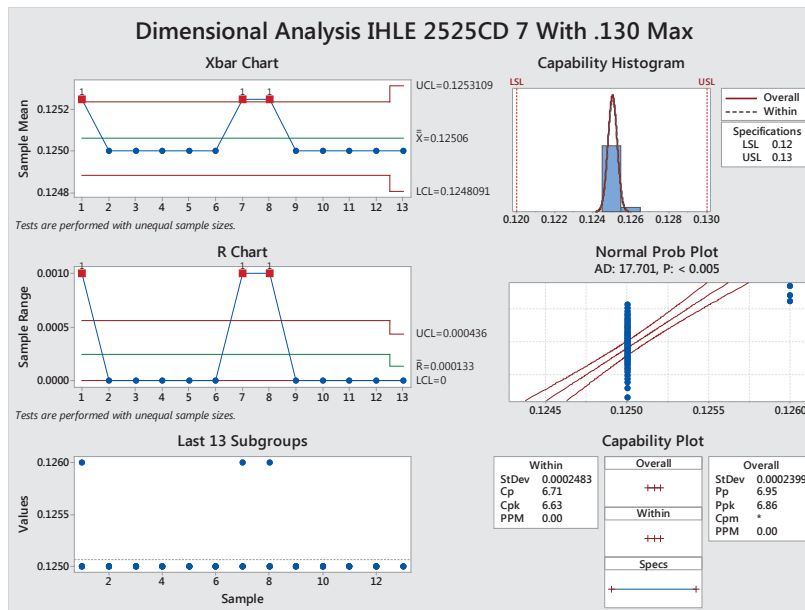
Dimensional Analysis IHLE 2525CD 6 With .065 Max



Production Part Approval Process

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Dimensional Analysis IHLE 2525CD





SECTION 10

PERFORMANCE TEST RESULTS





IHLE2525CDER3R3M5A IHLE2525CDER6R8M5A

TOP HEADER

- Parts were manufactured in Danshui, China location



IHLE2525CDER3R3M5A

TOP HEADER

Test #	Description	Ref. Spec. Meth / Cond	Test Conditions	End Point Δ requirements	Sample Size	Meas Temp							
0	3x reflow Preconditioning for lead-free products	ICP 10,373	As specified in sections 6.3 thru 6.4 except Visual per DPS-11,865 10X magnification										
1	Pre- and Post-Stress Electrical Test	IHLP Data Sheet	L (μ H) – 100KHz and 250mV DCR – 25°C Ambient	L = $\pm 15\%$ of initial, DCR = $\pm 15\%$ of initial	All tests requiring electrical data								
3	High Temp Exposure	IEC-60068 Part 2-2 test group BA	155C for 2000 hours, unpowered readings at 0, 250, 500, 1000 and 2000 hour intervals. Initial (0 hr.) and final (2000 hr.) readings at LT/RT/HT LT=Low Temperature=-55°C, RT=Room Temperature=+25°C, HT=High Temperature=+125°C for -A1/1A models. HT=High Temperature =+155°C for -5A models.	L = $\pm 20\%$ of initial, DCR = $\pm 20\%$ of initial	77			Inductance (μ H)			DC Resistance ($m\Omega$)		
								Initial	Final	% Δ	Initial	Final	% Δ
						-55 deg. C	Maximum	3.597	3.795	7.757	18.858	18.581	-0.755
							Minimum	3.273	3.479	4.802	18.282	18.020	-2.330
							Mean	3.442	3.643	5.831	18.614	18.333	-1.509
							Std Dev	0.068	0.063	0.517	0.113	0.120	0.324
						+25 deg. C		Initial	Final	% Δ	Initial	Final	% Δ
							Maximum	3.631	3.827	7.664	26.910	26.820	-0.264
							Minimum	3.307	3.510	4.875	26.300	26.160	-1.681
							Mean	3.475	3.674	5.752	26.675	26.549	-0.473
							Std Dev	0.070	0.063	0.498	0.147	0.155	0.183
						+155 deg. C		Initial	Final	% Δ	Initial	Final	% Δ
							Maximum	3.637	3.940	9.994	40.390	40.110	-0.305
							Minimum	3.323	3.613	7.712	39.060	38.740	-1.741
							Mean	3.487	3.787	8.611	39.731	39.439	-0.735
							Std Dev	0.072	0.070	0.393	0.282	0.314	0.297



IHLE2525CDER3R3M5A

TOP HEADER

								Inductance (μH)			DC Resistance (mΩ)		
								Initial	Final	%Δ	Initial	Final	%Δ
						-55 deg. C	Maximum	3.531	3.543	0.713	18.778	18.784	1.020
Mimimum	3.286	3.296	0.217	18.229	18.292		-1.500						
Mean	3.442	3.456	0.431	18.593	18.494		-0.527						
Std Dev	0.051	0.050	0.094	0.101	0.113		0.603						
+25 deg. C		Initial	Final	%Δ	Initial	Final	%Δ						
	Maximum	3.573	3.580	1.733	27.440	27.060	0.672						
	Mimimum	3.312	3.317	-0.148	26.570	26.420	-2.335						
	Mean	3.476	3.485	0.267	27.121	26.717	-1.490						
	Std Dev	0.053	0.053	0.195	0.165	0.133	0.504						
+155 deg. C		Initial	Final	%Δ	Initial	Final	%Δ						
	Maximum	3.590	3.594	0.420	40.550	40.460	1.799						
	Mimimum	3.313	3.316	-0.112	38.900	39.050	-1.513						
	Mean	3.486	3.490	0.104	39.808	39.639	-0.422						
	Std Dev	0.054	0.054	0.077	0.286	0.267	0.564						



IHLE2525CDER3R3M5A

TOP HEADER

4	Temperature Cycling	IEC-60068, Part 2.14 test group Na	-55°C to +125°C (+155° C for -5A models) dwell time ≤10 sec. no. of cycles = 1000 unpowered initial (0 cycles) and final 1000 cycles). Readings at LT/RT/HT	L= ±20% of initial, DCR = ±20% of initial	77			Inductance (μH)			DC Resistance (mΩ)		
								Initial	Final	%Δ	Initial	Final	%Δ
						-55 deg. C	Maximum	3.535	3.618	3.513	18.691	18.841	1.094
Minimum	3.243	3.351	1.743	18.233	18.196		-1.377						
Mean	3.429	3.517	2.591	18.453	18.471		0.097						
Std Dev	0.064	0.058	0.350	0.095	0.122		0.471						
+25 deg. C		Initial	Final	%Δ	Initial	Final	%Δ						
	Maximum	3.580	3.648	3.092	27.710	26.880	-0.592						
	Minimum	3.269	3.366	1.435	26.850	26.040	-5.166						
	Mean	3.464	3.540	2.199	27.204	26.583	-2.279						
	Std Dev	0.067	0.060	0.357	0.183	0.170	0.628						
+155 deg. C		Initial	Final	%Δ	Initial	Final	%Δ						
	Maximum	3.599	3.726	4.855	40.800	40.370	0.050						
	Minimum	3.280	3.435	3.413	39.180	37.800	-6.459						
	Mean	3.472	3.613	4.061	39.817	39.431	-0.967						
	Std Dev	0.067	0.063	0.318	0.320	0.495	1.046						

7	Biased Humidity	IEC-60068 Part 2-67	Temperature = 85°C ±20°C Humidity = 85% ±5% RH Duration = 1000 hours Power = No Power Initial (0hr.) and final (1000hr.) readings at LT/RT/HT	L= ±20% of initial, DCR = ±20% of initial	77			Inductance (μH)			DC Resistance (mΩ)		
								Initial	Final	%Δ	Initial	Final	%Δ
						-55 deg. C	Maximum	3.558	3.543	0.154	18.901	18.739	0.945
Minimum	3.240	3.115	-3.866	18.195	18.198		-2.876						
Mean	3.411	3.383	-0.822	18.651	18.424		-1.217						
Std Dev	0.070	0.085	0.739	0.121	0.101		0.744						
+25 deg. C		Initial	Final	%Δ	Initial	Final	%Δ						
	Maximum	3.590	3.570	-0.008	27.390	26.780	-0.450						
	Minimum	3.267	3.136	-3.992	26.600	25.850	-4.788						
	Mean	3.442	3.406	-1.031	26.977	26.541	-1.613						
	Std Dev	0.072	0.086	0.724	0.178	0.173	0.844						
+155 deg. C		Initial	Final	%Δ	Initial	Final	%Δ						
	Maximum	3.588	3.574	0.128	40.740	39.900	2.634						
	Minimum	3.276	3.154	-3.728	38.730	37.630	-6.300						
	Mean	3.450	3.422	-0.811	39.704	39.358	-0.864						
	Std Dev	0.073	0.086	0.708	0.396	0.403	1.351						



IHLE2525CDER3R3M5A

TOP HEADER

								Inductance (μH)			DC Resistance (mΩ)		
								Initial	Final	%Δ	Initial	Final	%Δ
8	Operational Life	MIL-STD-202, Method 108A	Temperature = 85°C for -1A/A1 models. Temperature =115° C for 5A models. Duration = 2000hrs. Power = As noted on the test request. Readings a 0, 250, 500, 1000 and 2000 hour intervals. Initial (0 hr.) and final (2000 hr.) readings at LT/RT/HT	L= ±20% of initial, DCR =±20% of initial	77	-55 deg. C	Maximum	3.525	3.619	4.147	19.089	18.798	0.263
							Mimimum	3.281	3.392	2.229	18.416	17.685	-4.229
							Mean	3.425	3.537	3.273	18.671	18.405	-1.423
							Std Dev	0.056	0.052	0.399	0.135	0.159	0.704
						+25 deg. C		Initial	Final	%Δ	Initial	Final	%Δ
							Maximum	3.557	3.670	4.919	27.460	27.110	2.741
							Mimimum	3.310	3.436	2.592	25.810	25.830	-2.968
							Mean	3.456	3.585	3.738	26.817	26.656	-0.590
						+155 deg. C		Initial	Final	%Δ	Initial	Final	%Δ
							Maximum	3.580	3.763	7.302	40.750	40.280	3.305
							Mimimum	3.324	3.498	4.296	38.430	36.720	-8.085
							Mean	3.471	3.669	5.706	39.785	39.671	-0.280
						Std Dev	0.059	0.059	0.508	0.416	0.447	1.259	
9	External Visual	MIL-STD-883G Method 2009.9	Inspect construction and workmanship.	Pass all criteria as defined in DPS-11,865 VA1	All	na	Pass						
10	Physical Dimensions	JESD22 Method JB-100	Verify physical dimensions per part specification	All parts within dimensional tolerance per data sheet	30	na	Pass						
12	Resistance to Solvents	MIL-STD-202G Method 215K	Add Aqueous wash chemical. OKEM Clean or equivalent. Do not use banned solvents.	Pass all criteria as defined in DPS-11,865 VA1 L= ±20% of initial, DCR =±20% of initial	5	na	Pass						



IHLE2525CDER3R3M5A

TOP HEADER

13	Mechanical Shock	IEC-60068 part 2.27 test group Ea with precondition per 0 above	Pulse Shape-Half Sine Normal Pulse Length 6ms Peak acceleration-100g No. shocks-6 each in both directions of each axis (total of 36) Initial and final readings at LT/RT/HT	L=±20% of initial, DCR =±20% of initial	30			Inductance (µH)			DC Resistance (mΩ)		
								Initial	Final	%Δ	Initial	Final	%Δ
						-55 deg. C	Maximum	3.532	3.543	0.511	18.787	18.701	0.233
Minimum	3.315	3.332	-0.482	18.392	18.354		-1.336						
Mean	3.429	3.441	0.359	18.570	18.526		-0.235						
Std Dev	0.056	0.056	0.172	0.105	0.078		0.380						
+25 deg. C		Initial	Final	%Δ	Initial	Final	%Δ						
	Maximum	3.566	3.577	0.474	26.840	26.910	2.700						
	Minimum	3.345	3.355	0.165	25.560	26.250	-0.037						
	Mean	3.459	3.472	0.365	26.630	26.719	0.337						
+155 deg. C	Std Dev	0.057	0.057	0.071	0.229	0.127	0.482						
		Initial	Final	%Δ	Initial	Final	%Δ						
	Maximum	3.571	3.573	0.297	40.060	40.500	3.191						
	Minimum	3.358	3.361	-0.005	38.540	39.400	-0.574						
	Mean	3.471	3.475	0.098	39.565	39.755	0.488						
	Std Dev	0.057	0.057	0.062	0.345	0.206	0.877						

14	Vibration	IEC-60068 PART 2-6 TEST GROUP Fc. With precondition per 0 above	Pulse Shape-sine wave range of frequency 1 10-55Hz. Amplitude ±0.75mm Range of frequency 2 55-2000Hz Amplitude; 10G Frequency Sweep: 1 oct./min. Duration: 24 h each of 3 axis. Initial and final readings at LT/RT/HT	L=±20% of initial, DCR =±20% of initial	30			Inductance (µH)			DC Resistance (mΩ)		
								Initial	Final	%Δ	Initial	Final	%Δ
						-55 deg. C	Maximum	3.588	3.600	0.726	18.887	18.882	0.313
Minimum	3.309	3.330	0.270	18.441	18.446		-0.577						
Mean	3.443	3.459	0.479	18.640	18.638		-0.008						
Std Dev	0.072	0.070	0.107	0.110	0.098		0.210						
+25 deg. C		Initial	Final	%Δ	Initial	Final	%Δ						
	Maximum	3.617	3.627	0.708	27.040	27.060	0.189						
	Minimum	3.341	3.359	0.215	26.450	26.460	-0.075						
	Mean	3.476	3.491	0.422	26.700	26.721	0.077						
+155 deg. C	Std Dev	0.073	0.072	0.100	0.147	0.146	0.068						
		Initial	Final	%Δ	Initial	Final	%Δ						
	Maximum	3.631	3.631	0.153	40.460	40.480	0.100						
	Minimum	3.356	3.359	-0.088	39.240	39.140	-0.558						
	Mean	3.489	3.490	0.040	39.825	39.757	-0.170						
	Std Dev	0.074	0.073	0.049	0.300	0.357	0.187						



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TOP HEADER

								Inductance (μH)			DC Resistance (mΩ)		
								Initial	Final	%Δ	Initial	Final	%Δ
Bump	IEC-60068 part 2-29 test group Eb with precondition per 0 above.	Pulse shape: half sine Nominal pulse length: 6 ms Peak Acceleration: 40g No. of shocks: 4000 each mechanical axis. Initial and final readings at LT/RT/HT	L=±20% of initial, DCR =±20% of initial	30	-55 deg. C	Maximum	3.513	3.525	0.539	18.926	18.568	-0.038	
						Minimum	3.324	3.339	0.092	18.366	18.278	-1.976	
						Mean	3.429	3.442	0.383	18.622	18.472	-0.798	
						Std Dev	0.051	0.050	0.098	0.147	0.076	0.629	
					+25 deg. C		Initial	Final	%Δ	Initial	Final	%Δ	
						Maximum	3.540	3.555	0.672	26.860	26.900	1.956	
						Minimum	3.347	3.363	0.212	25.560	26.030	-1.828	
						Mean	3.461	3.475	0.405	26.606	26.624	0.068	
						Std Dev	0.051	0.050	0.098	0.269	0.219	0.551	
					+155 deg. C		Initial	Final	%Δ	Initial	Final	%Δ	
						Maximum	3.549	3.554	0.144	40.130	40.270	1.114	
						Minimum	3.358	3.359	-0.068	39.390	38.910	-1.965	
Mean	3.473	3.475	0.075	39.761		39.741	-0.050						
	Std Dev	0.052	0.051	0.046	0.200	0.337	0.677						

15	Resistance to Solder Heat	MIL-STD-202G Method 210F Condition K	IR/convection reflow. 250 ± 5°C for 30 ± 5sec. Ramp rate 1°C/s to 4°C/; Above 183°C for 90s-120s	L= ±20% of initial, DCR = ±20% of initial	30			Inductance (μH)			DC Resistance (mΩ)		
								Initial	Final	%Δ	Initial	Final	%Δ
						+25 deg. C	Maximum	3.485	3.567	3.136	27.180	27.190	0.705
							Minimum	3.145	3.240	1.995	26.480	26.580	-0.037
							Mean	3.335	3.423	2.641	26.959	27.021	0.229
							Std Dev	0.076	0.073	0.263	0.186	0.171	0.213

17	ESD	AEC-Q200-002	Determine the Classification of the part.	L= ±20% of initial, DCR = ±20% of initial	15			Inductance (μH)			DC Resistance (mΩ)		
								Initial	25KV	%Δ	Initial	25KV	%Δ
						+25 deg. C	Maximum	3.416	3.648	7.245	27.030	27.260	0.964
							Minimum	3.219	3.411	0.737	26.790	27.010	0.222
							Mean	3.316	3.529	6.451	26.932	27.135	0.755
							Std Dev	0.054	0.061	1.718	0.075	0.087	0.186

18	Solderability	J-STD-002C Method B1	4 hours @ 155°C dry heat @ 255°C. 90° dipping angle.	95% or greater coverage on "A" (seating plane) per J-STD-002C.	15	NA	Pass					
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IHLE2525CDER3R3M5A

TOP HEADER

19	Electrical Characterization	User Specification	Min, Max, Mean, and Standard Deviation @ Min (-55C), Room, and Max (+125C) operating temperatures. After mounted, allow +/-5% shift DCR at room temp. -55C/+125C DCR Max calculated using temp conversion for copper: $R_2 = [(T_2 + 234.5) / (234.5 + T_A)] * 1.05R_A$ (A = Ambient, 2 = new con)	Final Test: L=±20% of initial, DCR per calculated limits described in test conditions. L test for -55C & +125C = ±20% initial	30			Inductance (μH)			DC Resistance (mΩ)		
								Initial			Initial		
						-55 deg. C	Maximum	3.513			18.926		
							Minimum	3.324			18.366		
							Mean	3.429			18.622		
							Std Dev	0.051			0.147		
						+25 deg. C		Initial			Initial		
							Maximum	3.540			26.860		
							Minimum	3.347			25.560		
							Mean	3.461			26.606		
							Std Dev	0.051			0.269		
						+155 deg. C		Initial			Initial		
							Maximum	3.549			40.130		
							Minimum	3.358			39.390		
							Mean	3.473			39.761		
							Std Dev	0.052			0.200		
21	Board Flex	AEC-Q200-005 Appendix 2	2mm minimum flex for 60 (+5) sec	Pass all criteria as defined in DPS-11,865 VA1 L=±20% of initial, DCR =±20% of initial	30			Inductance (μH)			DC Resistance (mΩ)		
								Initial	Final	%Δ	Initial	Final	%Δ
						+25 deg. C	Maximum	3.597	3.495	-1.407	27.230	27.320	0.924
							Minimum	3.538	3.142	-12.644	27.060	26.900	-1.030
							Mean	3.558	3.318	-6.716	27.157	27.109	-0.176
							Std Dev	0.028	0.090	2.744	0.073	0.110	0.482
22	Terminal Strength	AEC-Q200-006 Appendix 1	Force of 1.8kg (17.7 N) for 60 seconds	Pass all criteria as defined in DPS-11,865 VA1 L=±20% of initial, DCR =±20% of initial	30			Inductance (μH)			DC Resistance (mΩ)		
								Initial	Final	%Δ	Initial	Final	%Δ
						+25 deg. C	Maximum	3.515	3.465	-0.984	27.370	27.350	0.406
							Minimum	3.228	3.190	-1.450	26.690	26.590	-0.406
							Mean	3.363	3.322	-1.215	27.030	27.025	-0.017
							Std Dev	0.082	0.080	0.097	0.148	0.157	0.228



IHLE2525CDER6R8M5A

Test #	Description	Ref. Spec. Meth / Cond	Test Conditions	End Point Δ requirements	Sample Size	Meas Temp							
0	3x reflow Preconditioning for lead-free products	ICP 10,373	As specified in sections 6.3 thru 6.4 except Visual per DPS-11,865 10X magnification										
1	Pre- and Post-Stress Electrical Test	IHLP Data Sheet	L (μ H) – 100KHz and 250mV DCR – 25°C Ambient	L = $\pm 15\%$ of initial, DCR = $\pm 15\%$ of initial	All tests requiring electrical data								
3	High Temp Exposure	IEC-60068 Part 2-2 test group BA	155C for 2000 hours, unpowered readings at 0, 250, 500, 1000 and 2000 hour intervals. Initial (0 hr.) and final (2000 hr.) readings at LT/RT/HT LT=Low Temperature=-55°C, RT=Room Temperature= $\pm 25^\circ$ C, HT=High Temperature= $\pm 125^\circ$ C for -A1/1A models. HT=High Temperature = $\pm 155^\circ$ C for -5A models.	L = $\pm 20\%$ of initial, DCR = $\pm 20\%$ of initial	77			Inductance (μ H)			DC Resistance ($m\Omega$)		
						-55 deg. C		Initial	Final	% Δ	Initial	Final	% Δ
							Maximum	7.113	7.437	6.581	33.870	33.470	0.813
							Minimum	6.361	6.731	3.225	32.990	32.670	-2.672
							Mean	6.649	6.984	5.050	33.440	33.035	-1.207
							Std Dev	0.152	0.138	0.557	0.217	0.171	0.840
						+25 deg. C		Initial	Final	% Δ	Initial	Final	% Δ
							Maximum	7.171	7.503	6.793	48.580	48.410	0.417
							Minimum	6.396	6.790	3.225	47.740	47.370	-0.894
							Mean	6.692	7.049	5.342	48.109	47.895	-0.443
							Std Dev	0.157	0.142	0.545	0.195	0.195	0.331
						+155 deg. C		Initial	Final	% Δ	Initial	Final	% Δ
							Maximum	7.140	7.661	8.296	72.460	72.200	0.625
							Minimum	6.405	6.913	6.244	70.390	69.980	-1.760
							Mean	6.693	7.182	7.299	71.582	71.150	-0.601
							Std Dev	0.152	0.155	0.346	0.457	0.437	0.506



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								Inductance (μH)			DC Resistance (mΩ)		
								Initial	Final	%Δ	Initial	Final	%Δ
						-55 deg. C	Maximum	7.110	7.124	0.779	33.950	33.850	0.774
Mimimum	6.291	6.314	-0.112	33.120	32.820		-2.389						
Mean	6.636	6.657	0.328	33.489	33.210		-0.832						
Std Dev	0.171	0.167	0.139	0.171	0.241		0.538						
+25 deg. C		Initial	Final	%Δ	Initial	Final	%Δ						
	Maximum	7.183	7.192	0.731	48.720	48.720	0.418						
	Mimimum	6.318	6.333	-1.005	47.600	47.570	-0.910						
	Mean	6.679	6.694	0.224	48.068	48.031	-0.076						
	Std Dev	0.176	0.171	0.209	0.210	0.234	0.232						
+155 deg. C		Initial	Final	%Δ	Initial	Final	%Δ						
	Maximum	7.183	7.190	0.483	72.800	72.560	1.640						
	Mimimum	6.314	6.330	-0.169	70.050	69.950	-1.141						
	Mean	6.677	6.694	0.264	71.444	71.133	-0.435						
	Std Dev	0.174	0.174	0.167	0.567	0.553	0.377						



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4	Temperature Cycling	IEC-60068, Part 2.14 test group Na	-55°C to +125°C (+155° C for -5A models) dwell time = 30 min. transfer time ≤10 sec. no. of cycles = 1000 unpowered initial (0 cycles) and final 1000 cycles). Readings at LT/RT/HT	L=±20% of initial, DCR = ±20% of initial	77			Inductance (μH)			DC Resistance (mΩ)		
								Initial	Final	%Δ	Initial	Final	%Δ
						-55 deg. C	Maximum	6.956	7.058	2.483	34.390	33.720	0.091
Minimum	6.247	6.402	0.876	33.040	32.860		-2.104						
Mean	6.623	6.727	1.572	33.650	33.230		-1.245						
Std Dev	0.144	0.136	0.285	0.218	0.196		0.467						
+25 deg. C		Initial	Final	%Δ	Initial	Final	%Δ						
	Maximum	7.012	7.108	2.267	49.000	48.480	0.168						
	Minimum	6.278	6.418	0.752	47.470	47.340	-1.282						
	Mean	6.662	6.759	1.451	48.238	47.796	-0.915						
Std Dev	0.149	0.139	0.300	0.243	0.228	0.322							
+155 deg. C		Initial	Final	%Δ	Initial	Final	%Δ						
	Maximum	7.019	7.210	3.159	73.480	72.630	0.409						
	Minimum	6.313	6.504	2.190	70.290	70.160	-1.846						
	Mean	6.671	6.846	2.623	71.915	71.179	-1.022						
Std Dev	0.146	0.145	0.200	0.551	0.498	0.471							

7	Biased Humidity	IEC-60068 Part 2-67	Temperature = 85°C ±20°C Humidity = 85% ±5% RH Duration = 1000 hours Power = No Pow er Initial (0hr.) and final (1000hr.) readings at LT/RT/HT	L=±20% of initial, DCR = ±20% of initial	77			Inductance (μH)			DC Resistance (mΩ)		
								Initial	Final	%Δ	Initial	Final	%Δ
						-55 deg. C	Maximum	6.927	6.888	-0.092	33.790	33.720	1.200
Minimum	6.157	6.113	-1.847	32.930	32.790		-1.721						
Mean	6.613	6.564	-0.746	33.222	33.193		-0.085						
Std Dev	0.159	0.164	0.372	0.177	0.219		0.706						
+25 deg. C		Initial	Final	%Δ	Initial	Final	%Δ						
	Maximum	6.970	6.918	-0.188	48.410	48.890	1.084						
	Minimum	6.206	6.148	-1.923	47.530	47.590	-0.398						
	Mean	6.658	6.602	-0.834	48.004	48.208	0.426						
Std Dev	0.162	0.166	0.370	0.200	0.297	0.494							
+155 deg. C		Initial	Final	%Δ	Initial	Final	%Δ						
	Maximum	6.968	6.966	0.325	72.470	72.350	0.508						
	Minimum	6.219	6.174	-1.332	69.870	69.870	-1.928						
	Mean	6.654	6.629	-0.376	71.330	71.072	-0.361						
Std Dev	0.160	0.170	0.391	0.517	0.565	0.650							



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								Inductance (μH)			DC Resistance (mΩ)		
								Initial	Final	%Δ	Initial	Final	%Δ
8	Operational Life	MIL-STD-202, Method 108A	Temperature = 85°C for -1A/A1 models. Temperature =115° C for 5A models. Duration = 2000hrs. Pow er = As noted on the test request. Readings a 0, 250, 500, 1000 and 2000 hour intervals. Initial (0 hr.) and final (2000 hr.) readings at LT/RT/HT	L= ±20% of initial, DCR = ±20% of initial	77	-55 deg. C	Maximum	6.899	6.990	3.274	34.220	33.980	0.982
							Mimimum	6.113	6.313	1.261	33.310	32.800	-3.072
							Mean	6.578	6.706	1.955	33.674	33.307	-1.086
							Std Dev	0.183	0.167	0.451	0.222	0.268	1.027
						+25 deg. C		Initial	Final	%Δ	Initial	Final	%Δ
							Maximum	6.948	7.086	4.008	48.770	49.290	2.071
							Mimimum	6.133	6.379	1.896	47.920	47.000	-2.887
							Mean	6.613	6.785	2.609	48.376	48.007	-0.761
						+155 deg. C		Initial	Final	%Δ	Initial	Final	%Δ
							Maximum	6.930	7.163	4.493	73.140	72.460	0.480
							Mimimum	6.140	6.414	2.479	70.890	69.130	-3.856
							Mean	6.611	6.835	3.399	72.050	71.336	-0.988
						Std Dev	0.190	0.187	0.494	0.505	0.579	0.930	
9	External Visual	MIL-STD-883G Method 2009.9	Inspect construction and workmanship.	Pass all criteria as defined in DPS-11,865 VA1	All	na	Pass						
10	Physical Dimensions	JESD22 Method JB-100	Verify physical dimensions per part specification	All parts within dimensional tolerance per data sheet	30	na	Pass						
12	Resistance to Solvents	MIL-STD-202G Method 215K	Add Aqueous wash chemical. OKEM Clean or equivalent. Do not use banned solvents.	Pass all criteria as defined in DPS-11,865 VA1 L= ±20% of initial, DCR = ±20% of initial	5	na	Pass						



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13	Mechanical Shock	IEC-60068 part 2.27 test group Ea with precondition per 0 above	Pulse Shape-Half Sine Normal Pulse Length 6ms Peak acceleration-100g No. shocks-6 each in both directions of each axis (total of 36) Initial and final readings at LT/RT/HT	L=±20% of initial, DCR =±20% of initial	30			Inductance (μH)			DC Resistance (mΩ)		
								Initial	Final	%Δ	Initial	Final	%Δ
						-55 deg. C	Maximum	6.874	6.916	2.375	33.790	34.010	0.651
							Mimimum	6.159	6.260	0.384	33.080	33.150	0.030
							Mean	6.542	6.609	1.024	33.391	33.485	0.281
							Std Dev	0.195	0.180	0.441	0.192	0.219	0.159
						+25 deg. C		Initial	Final	%Δ	Initial	Final	%Δ
							Maximum	6.928	6.975	2.455	48.650	49.380	1.696
							Mimimum	6.168	6.278	0.549	47.770	48.300	0.809
							Mean	6.578	6.650	1.102	48.220	48.819	1.242
						+155 deg. C	Std Dev	0.200	0.185	0.448	0.232	0.319	0.242
								Initial	Final	%Δ	Initial	Final	%Δ
							Maximum	6.941	6.949	0.276	72.170	72.200	0.793
Mimimum	6.234	6.243	0.091	70.630	71.030		-0.153						
Mean	6.611	6.622	0.161	71.585	71.604	0.026							
Std Dev	0.188	0.188	0.043	0.320	0.285	0.159							

14	Vibration	IEC-60068 PART 2-6 TEST GROUP Fc. With precondition per 0 above	Pulse Shape-sine wave range of frequency 1 10-55Hz. Amplitude ±0.75mm Range of frequency 2 55-2000Hz Amplitude; 10G Frequency Sweep: 1 oct./min. Duration: 24 h each of 3 axis. Initial and final readings at LT/RT/HT	L=±20% of initial, DCR =±20% of initial	30			Inductance (μH)			DC Resistance (mΩ)		
								Initial	Final	%Δ	Initial	Final	%Δ
						-55 deg. C	Maximum	7.098	7.127	1.072	33.790	33.720	-0.119
							Mimimum	6.145	6.211	0.308	33.350	33.120	-0.690
							Mean	6.670	6.707	0.567	33.585	33.440	-0.432
							Std Dev	0.219	0.211	0.178	0.122	0.159	0.169
						+25 deg. C		Initial	Final	%Δ	Initial	Final	%Δ
							Maximum	7.171	7.215	1.164	48.660	49.030	0.948
							Mimimum	6.177	6.249	0.418	48.010	48.160	0.250
							Mean	6.716	6.760	0.671	48.373	48.665	0.604
						+155 deg. C	Std Dev	0.227	0.221	0.161	0.179	0.239	0.192
								Initial	Final	%Δ	Initial	Final	%Δ
							Maximum	7.190	7.208	0.345	72.880	72.440	-0.469
Mimimum	6.202	6.216	0.105	71.680	71.040		-1.169						
Mean	6.722	6.737	0.227	72.357	71.856	-0.693							
Std Dev	0.226	0.227	0.060	0.342	0.360	0.137							



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								Inductance (μH)			DC Resistance (mΩ)				
								Initial	Final	%Δ	Initial	Final	%Δ		
Bump	IEC-60068 part 2-29 test group Eb with precondition per 0 above.	Pulse shape: half sine Nominal pulse length: 6 ms Peak Acceleration: 40g No. of shocks: 4000 each mechanical axis. Initial and final readings at LT/RT/HT	L=±20% of initial, DCR =±20% of initial	30	-55 deg. C	Maximum	6.966	7.007	1.344	33.650	33.790	0.809			
						Mimimum	6.236	6.279	0.273	33.090	33.290	0.239			
						Mean	6.584	6.636	0.785	33.347	33.529	0.547			
						Std Dev	0.192	0.186	0.202	0.120	0.112	0.138			
					+25 deg. C		Initial	Final	%Δ	Initial	Final	%Δ			
						Maximum	7.025	7.071	1.376	48.710	49.720	2.199			
						Mimimum	6.271	6.315	0.385	47.910	48.680	1.217			
						Mean	6.627	6.683	0.844	48.286	49.055	1.593			
					+155 deg. C	Std Dev	0.198	0.193	0.189	0.205	0.251	0.272			
							Initial	Final	%Δ	Initial	Final	%Δ			
						Maximum	7.024	7.036	0.263	73.660	73.130	0.757			
						Mimimum	6.276	6.288	0.127	71.140	71.450	-0.720			
						Mean	6.645	6.657	0.190	72.089	72.271	0.254			
Std Dev	0.195	0.195	0.041	0.547	0.414	0.256									
15	Resistance to Solder Heat	MIL-STD-202G Method 210F Condition K	IR/convection reflow. 250 ± 5°C for 30 ± 5sec. Ramp rate 1°C/s to 4°C/; Above 183°C for 90s-120s	L= ±20% of initial, DCR = ±20% of initial	30			Inductance (μH)			DC Resistance (mΩ)				
								Initial	Final	%Δ	Initial	Final	%Δ		
								+25 deg. C	Maximum	6.760	6.894	4.366	49.080	48.920	-0.062
									Mimimum	6.111	6.378	1.654	48.360	48.180	-0.430
									Mean	6.461	6.645	2.861	48.653	48.527	-0.259
Std Dev	0.173	0.148	0.769	0.182	0.171	0.108									
17	ESD	AEC-Q200-002	Determine the Classification of the part.	L= ±20% of initial, DCR = ±20% of initial	15			Inductance (μH)			DC Resistance (mΩ)				
								Initial	25KV	%Δ	Initial	25KV	%Δ		
								+25 deg. C	Maximum	6.808	6.764	0.881	48.860	48.850	0.062
									Mimimum	6.138	6.147	-0.699	48.110	47.940	-0.783
									Mean	6.518	6.508	-0.144	48.483	48.358	-0.259
Std Dev	0.207	0.197	0.505	0.185	0.253	0.278									
18	Solderability	J-STD-002C Method B1	4 hours @ 155°C dry heat @ 255°C. 90° dipping angle.	95% or greater coverage on "A" (seating plane) per J-STD-002C	15	NA	Pass								



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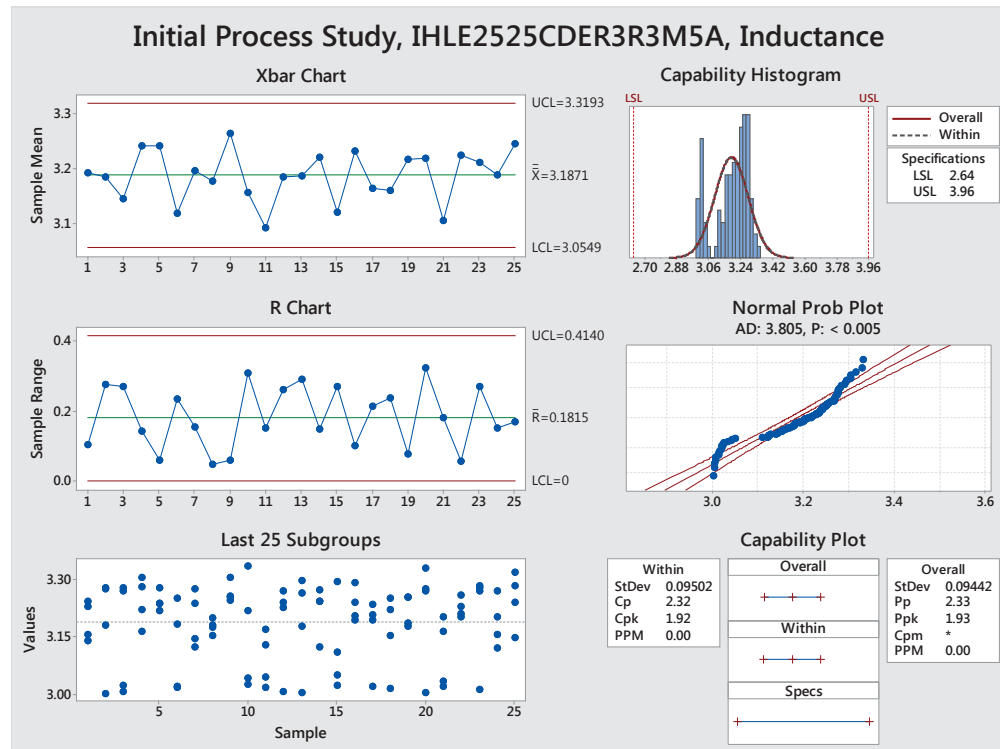
19	Electrical Characterization	User Specification	Min, Max, Mean, and Standard Deviation @ Min (-55C), Room, and Max (+125C) operating temperatures. After mounted, allow +/-5% shift DCR at room temp. -55C/+125C DCR Max calculated using temp conversion for copper: $R_2 = [(T_2 + 234.5) / (234.5 + T_A)] * 1.05R_A$ (A = Ambient, 2 = new con)	Final Test: L=±20% of initial, DCR per calculated limits described in test conditions. L test for -55C & +125C = ±20% initial	30			Inductance (μH)			DC Resistance (mΩ)		
								Initial			Initial		
						-55 deg. C	Maximum	6.966			33.650		
							Minimum	6.236			33.090		
							Mean	6.584			33.347		
							Std Dev	0.192			0.120		
						+25 deg. C		Initial			Initial		
							Maximum	7.025			48.710		
							Minimum	6.271			47.910		
							Mean	6.627			48.286		
							Std Dev	0.198			0.205		
						+155 deg. C		Initial			Initial		
							Maximum	7.024			73.660		
							Minimum	6.276			71.140		
							Mean	6.645			72.089		
							Std Dev	0.195			0.547		
21	Board Flex	AEC-Q200-005 Appendix 2	2mm minimum flex for 60 (+5) sec	Pass all criteria as defined in DPS-11,865 VA1 L=±20% of initial, DCR =±20% of initial	30			Inductance (μH)			DC Resistance (mΩ)		
								Initial	Final	%Δ	Initial	Final	%Δ
						+25 deg. C	Maximum	6.843	6.886	0.826	49.250	49.390	0.284
							Minimum	6.120	6.152	0.362	48.650	48.500	-0.349
							Mean	6.466	6.507	0.634	48.927	48.873	-0.112
							Std Dev	0.177	0.179	0.092	0.176	0.192	0.215
22	Terminal Strength	AEC-Q200-006 Appendix 1	Force of 1.8kg (17.7 N) for 60 seconds	Pass all criteria as defined in DPS-11,865 VA1 L=±20% of initial, DCR =±20% of initial	30			Inductance (μH)			DC Resistance (mΩ)		
								Initial	Final	%Δ	Initial	Final	%Δ
						+25 deg. C	Maximum	6.886	6.917	0.466	48.820	48.910	0.597
							Minimum	6.310	6.333	-0.188	48.060	48.220	0.021
							Mean	6.562	6.585	0.342	48.426	48.590	0.339
							Std Dev	0.150	0.150	0.142	0.186	0.189	0.180

Production Part Approval Process

The following PPAP documentation is assembled according to
AIAG, 4th Edition PPAP Manual and applicable customer requirements

Initial Process Study IHLE 2525CDER3R3M5A, Inductance

Inductance (uH)							
1	3.22999	26	3.12315	51	3.29541	76	3.25204
2	3.14086	27	3.23643	52	3.00494	77	3.32862
3	3.15585	28	3.14469	53	3.12288	78	3.26963
4	3.24236	29	3.2002	54	3.27128	79	3.00463
5	3.18132	30	3.15285	55	3.24229	80	3.27339
6	3.27688	31	3.17341	56	3.24219	81	3.16353
7	3.27582	32	3.18114	57	3.05033	82	3.20104
8	3.00271	33	3.30377	58	3.02334	83	3.02053
9	3.00791	34	3.25625	59	3.29332	84	3.03368
10	3.02431	35	3.24419	60	3.109	85	3.21003
11	3.27713	36	3.25286	61	3.23988	86	3.20238
12	3.26806	37	3.2179	62	3.19256	87	3.25927
13	3.28031	38	3.0262	63	3.29185	88	3.22887
14	3.16497	39	3.04248	64	3.20461	89	3.01323
15	3.30529	40	3.33306	65	3.19295	90	3.26813
16	3.21945	41	3.12811	66	3.23377	91	3.27712
17	3.27601	42	3.04475	67	3.20824	92	3.28222
18	3.23685	43	3.1691	68	3.01974	93	3.27035
19	3.23676	44	3.01914	69	3.01412	94	3.12058
20	3.21795	45	3.26819	70	3.15421	95	3.20187
21	3.0174	46	3.23812	71	3.25024	96	3.15593
22	3.18192	47	3.22627	72	3.22147	97	3.23847
23	3.02031	48	3.00711	73	3.17764	98	3.31647
24	3.25092	49	3.26361	74	3.25248	99	3.28333
25	3.27532	50	3.17801	75	3.1852	100	3.14678



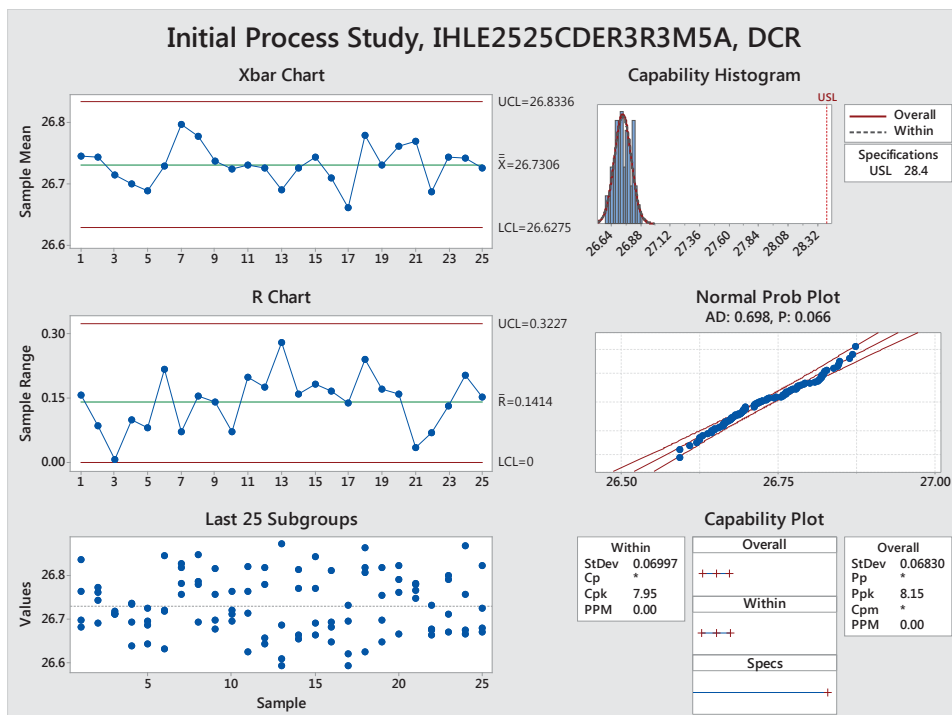


Production Part Approval Process

The following PPAP documentation is assembled according to
AIAG, 4th Edition PPAP Manual and applicable customer requirements

Initial Process Study IHLE 2525CDER3R3M5A, DC Resistance

DCR (mOhm)							
1	26.763	26	26.827	51	26.608	76	26.754
2	26.697	27	26.782	52	26.593	77	26.761
3	26.838	28	26.819	53	26.663	78	26.824
4	26.681	29	26.694	54	26.814	79	26.666
5	26.774	30	26.786	55	26.77	80	26.792
6	26.744	31	26.848	56	26.655	81	26.779
7	26.762	32	26.78	57	26.771	82	26.767
8	26.69	33	26.676	58	26.691	83	26.747
9	26.711	34	26.757	59	26.663	84	26.782
10	26.718	35	26.816	60	26.845	85	26.663
11	26.713	36	26.698	61	26.692	86	26.677
12	26.712	37	26.765	62	26.813	87	26.674
13	26.693	38	26.721	63	26.681	88	26.731
14	26.733	39	26.712	64	26.648	89	26.801
15	26.736	40	26.695	65	26.593	90	26.791
16	26.637	41	26.713	66	26.732	91	26.711
17	26.724	42	26.763	67	26.696	92	26.67
18	26.643	43	26.624	68	26.619	93	26.869
19	26.686	44	26.822	69	26.808	94	26.757
20	26.696	45	26.657	70	26.864	95	26.675
21	26.72	46	26.643	71	26.624	96	26.665
22	26.63	47	26.819	72	26.818	97	26.671
23	26.717	48	26.78	73	26.698	98	26.823
24	26.846	49	26.687	74	26.648	99	26.724
25	26.757	50	26.873	75	26.819	100	26.679

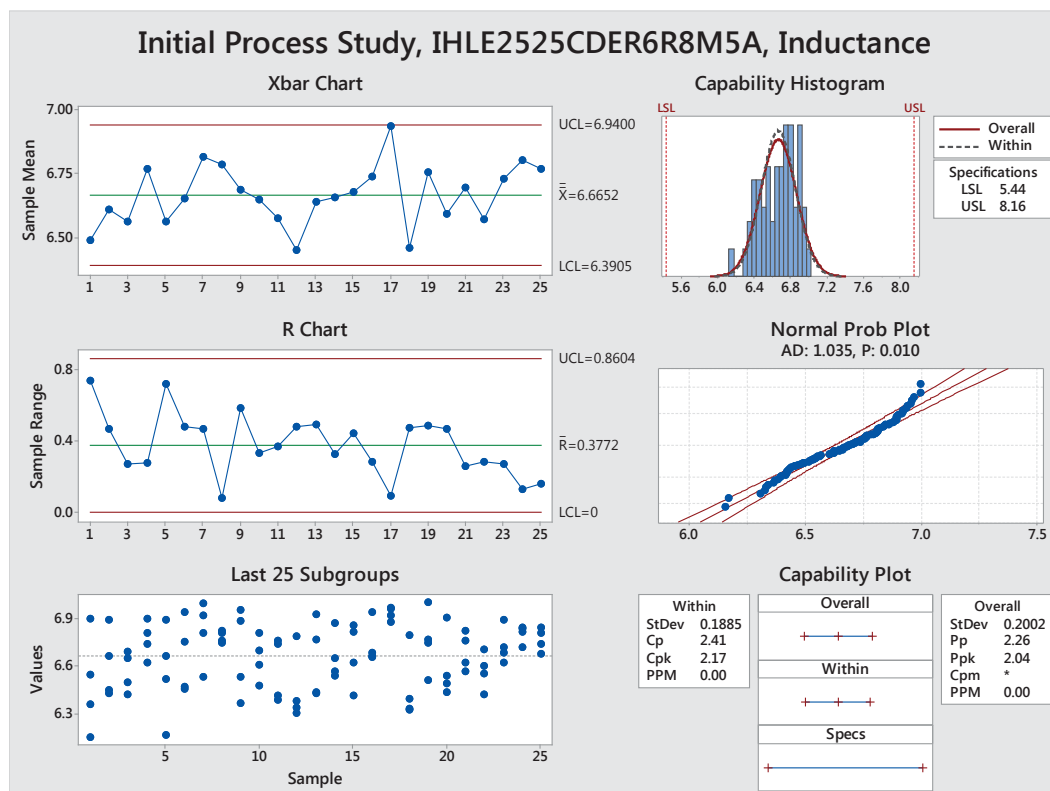


Production Part Approval Process

The following PPAP documentation is assembled according to
AIAG, 4th Edition PPAP Manual and applicable customer requirements

Initial Process Study IHLE2525CDER6R8M5A, Inductance

Inductance (uH)							
1	6.547	26	6.806	51	6.44	76	6.999
2	6.362	27	6.998	52	6.432	77	6.494
3	6.895	28	6.53	53	6.649	78	6.434
4	6.156	29	6.744	54	6.868	79	6.902
5	6.894	30	6.81	55	6.54	80	6.542
6	6.427	31	6.757	56	6.564	81	6.62
7	6.453	32	6.822	57	6.625	82	6.824
8	6.664	33	6.955	58	6.815	83	6.569
9	6.65	34	6.886	59	6.86	84	6.76
10	6.691	35	6.369	60	6.414	85	6.705
11	6.497	36	6.537	61	6.942	86	6.555
12	6.42	37	6.699	62	6.664	87	6.421
13	6.9	38	6.811	63	6.684	88	6.603
14	6.737	39	6.48	64	6.66	89	6.716
15	6.808	40	6.606	65	6.96	90	6.625
16	6.623	41	6.76	66	6.879	91	6.683
17	6.171	42	6.738	67	6.969	92	6.894
18	6.893	43	6.391	68	6.922	93	6.717
19	6.518	44	6.418	69	6.331	94	6.846
20	6.666	45	6.305	70	6.797	95	6.816
21	6.757	46	6.381	71	6.324	96	6.836
22	6.936	47	6.787	72	6.395	97	6.809
23	6.455	48	6.34	73	6.514	98	6.841
24	6.469	49	6.923	74	6.745	99	6.739
25	6.918	50	6.768	75	6.768	100	6.681

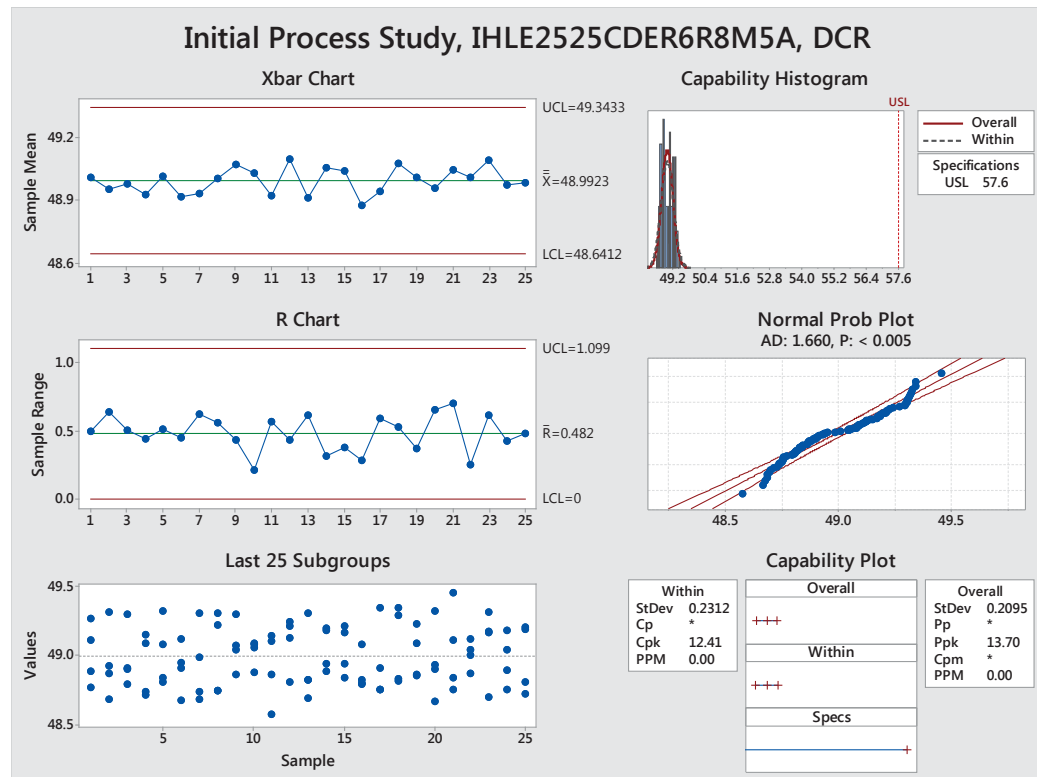


Production Part Approval Process

The following PPAP documentation is assembled according to AIAG, 4th Edition PPAP Manual and applicable customer requirements

Initial Process Study IHLE2525CDER6R8M5A, DC Resistance

DCR (mOhm)					
1	48.771	26	48.738	51	48.828
2	49.112	27	49.309	52	48.694
3	49.269	28	48.686	53	48.89
4	48.886	29	49.305	54	49.183
5	48.685	30	48.748	55	48.944
6	49.319	31	48.75	56	49.199
7	48.871	32	49.221	57	48.837
8	48.928	33	48.866	58	49.213
9	48.913	34	49.297	59	49.171
10	48.796	35	49.073	60	48.938
11	49.301	36	49.04	61	48.797
12	48.906	37	49.083	62	48.822
13	48.738	38	49.089	63	49.079
14	48.715	39	48.879	64	48.804
15	49.154	40	49.058	65	48.757
16	49.093	41	49.142	66	48.911
17	48.843	42	48.577	67	48.754
18	49.08	43	48.861	68	49.343
19	49.326	44	49.106	69	48.836
20	48.813	45	49.127	70	49.295
21	49.124	46	49.216	71	48.82
22	48.95	47	48.809	72	49.343
23	48.674	48	49.242	73	49.09
24	48.91	49	49.304	74	49.23
25	48.986	50	48.826	75	48.859
				100	49.192



Production Part Approval Process

**The following PPAP documentation is assembled according to
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Use the control buttons below to navigate through the PPAP sections.

Section 12: Qualified Laboratories

Vishay / Dale Electronics

1505 East Hwy 50 Yankton, SD 57078, USA Phone (605) 665-9301 Fax (605) 668-4247

ONE OF THE WORLD'S LARGEST MANUFACTURERS OF DISCRETE SEMICONDUCTORS AND PASSIVE COMPONENTS

Production Part Approval Process

**The following PPAP documentation is assembled according to
AIAG, 4th Edition PPAP Manual and applicable customer requirements**

Use the control buttons below to navigate through the PPAP sections.

Section 13: Appearance Approval Report

Inductors, like many other electronic components are specified for their electrical properties. There are no specific requirements stated for the physical appearance of inductors, e.g. color of inductors. Therefore, the Appearance Approval Report does not apply in this case.

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Section 14: Sample Product

Sample product from the Vishay Manufacturing Facility is available upon request

Production Part Approval Process

**The following PPAP documentation is assembled according to
AIAG, 4th Edition PPAP Manual and applicable customer requirements**

Use the control buttons below to navigate through the PPAP sections.

Section 15: Master Sample

Master Sample(s) will be retained at the Vishay Manufacturing Facility with a copy of the PPAP

Production Part Approval Process

**The following PPAP documentation is assembled according to
AIAG, 4th Edition PPAP Manual and applicable customer requirements**

Use the control buttons below to navigate through the PPAP sections.

[Section 16: Checking Aids](#)

Checking Aids are not required for this electronic component

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Use the control buttons below to navigate through the PPAP sections.

Section 19: Bulk Material Requirements

Bulk Material Requirements do not apply to this Electronic Component.



IHLP Standards of Manufacture

IHLP INTRODUCTION SURFACE IRREGULARITIES CRITERIA FOR REJECTION SUMMARY

INTRODUCTION

Scope

This document was written for the purpose of helping customers better understand the product they are purchasing. It will give the customer an idea as to the type of cosmetic irregularities that may occur from time to time during the manufacture of the component itself or during customer use of the component.

This document also discusses the criteria that have been developed for rejection of irregularities that are determined to be excessive.

While it would be desirable to have cosmetically perfect IHLP inductors, the powdered iron manufacturing technique has cosmetic limitations.

Certified test labs have performed extensive environmental testing on IHLP's with and without cosmetic imperfections according to AEC-Q200 standards for such tests as thermal shock, mechanical shock, vibration, humidity and others. This testing has shown that the cosmetic imperfections listed in this document do not affect the performance or reliability of the IHLP inductor. Test results are available upon request.

Product

The IHLP inductor is unique from most inductors. The inductor body is a soft magnetic composite (SMC), not a ferrite. It is made from an iron powder mixture and cemented together using a resin binder. This powder mixture, when pressed around the inductor coil, greatly enhances the electrical properties of the inductor and gives protection from environmental forces. After pressing, the component is cured in an oven to increase the bonding strength of the resin binders with the iron powder, yielding excellent electrical and physical properties.

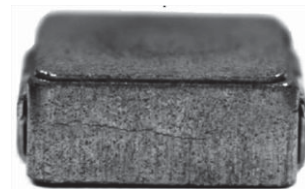
The IHLP inductor provides the best combination of:

- Inductance
- Low Core Loss
- Saturation
- Temperature Stability
- Smallest Footprint
- Lowest Profile

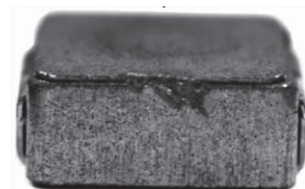
Surface irregularities

The following pages include descriptions of the most common irregularities seen on IHLP inductors. Common causes are described along with variations in their magnitude. Customers may at some time see one or all of these irregularities.

Those that are determined to adversely affect the customer's use of the component are rejected, but minor (acceptable) irregularities will occasionally be present. With the use of this guide, a customer will better understand the effect of each irregularity.



Cracks



Chips



Oxidation

IHLP Standards of Manufacture

CRACKS

Cracks within the inductor body are unavoidable during the manufacturing process. Small cracks are caused by die wall friction when the parts are ejected during the pressing process and by expansion of the coil during the process of curing the resin binder in the powdered iron body. Unlike ferrite material, cracks on the IHLP body do not affect the electrical performance of the component.

Reliability testing has shown that even cracks in excess of 0.005" will not cause the component to fail electrically or physically in field application. Acceptance widths are adopted based on the ability to detect cracks both at the component and circuit level.



Terminal area crack, acceptable

Cracks coming from the top corner of the terminal are a normal occurrence and are caused by terminal expansion during curing operations.



Negligible crack, acceptable

Negligible cracks are those that are nearly invisible without magnification.



Minor crack, acceptable

Minor cracks are those that are visible without magnification but are not apparent without close inspection.



Moderate crack, rejectable

Moderate cracks are those that are obvious upon examination and continue across most of the component.



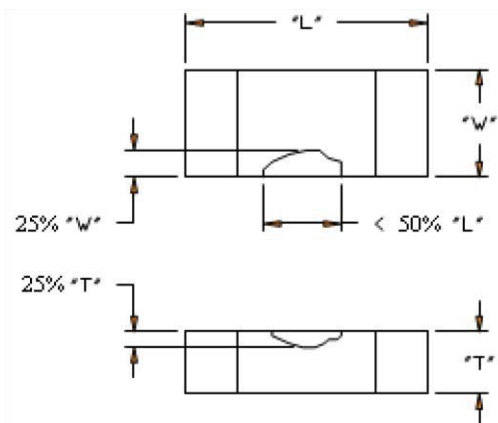
Major crack, rejectable

Major cracks are those that are obvious to a customer and would possibly result in large chip-outs that would expose the coil and lead frame.

IHLP Standards of Manufacture

CHIPS

Chipping of the inductor body can occur during normal processing and testing of the inductor. The acceptance criteria for chipping vary with the size of the component, but current acceptance standards are based on IPCA-610. The effect of chipping is negligible as long as the inductor coil is not showing. See IPC standard for class 1 and 2 components below.



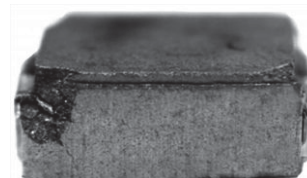
T	25 % of the thickness
W	25 % of the width
L	50 % of the length

Chips typically occur on the edges and corners of the inductor body. They are slightly darker in color and rougher in appearance than the surrounding material.



Minor chipping, acceptable

Minor chips in the inductor body are those that are typically shallow imperfections that occur on the corners and edge of components. No coil wire or lead frame is showing and the chip does not affect the performance or reliability of the component.



Major chipping, rejectable

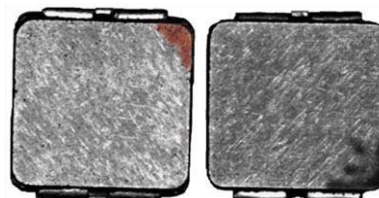
Major chips in the inductor body are those that are very obvious to the customer and may expose the wire coil or lead frame.

OXIDATION

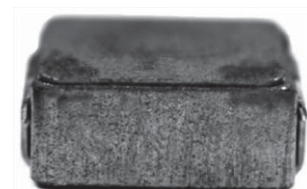
The IHLP inductor is predominately iron and oxidation may occur in a small percentage of the inductors. Resin binders give moderate protection, but some slight oxidation may occur. All components should be stored away from heat, humidity and ionized atmospheres as much as possible before mounting.

Basic steps should be taken in order to limit surface oxidation, including keeping the IHLP inductors sealed in their packaging until PCB mounting.

In the case that oxidation does occur, the effects are contained to the surface of the component and do not penetrate into the core material. No electrical effects have ever been documented due to oxidation of the IHLP product. Oxidation should never be considered a reliability risk.



Top view



Side view

IHLP Standards of Manufacture

OTHER

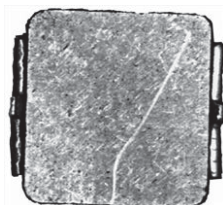
A very small number of other irregularities have been reported. These occur at an exceedingly low rate and typically do not affect the components electrically. These include:

Foreign material may be seen pressed into the upper terminals. This material is of the same material as the inductor body and should not be a reason for rejection unless solderability is affected.



Foreign material: Acceptable

Scratches may be seen on the surface of the inductor body. Scratches are an acceptable surface irregularity.



Scratch: Acceptable

SUMMARY

The IHLP inductor is comprised of an iron powder body compressed around a coil. Due to the fact that this iron powder body is not solid like ferrite material, irregularities such as cracks and chips do not affect the electrical properties, or the reliability of the component. Criteria have been determined for the acceptability of the components that allow for a robust manufacturing process as well as an acceptable degree of cosmetic irregularity.

Reliability testing has been done on the effects of cracking of the iron powder body and on the oxidation of the iron particles that are present on the surface. Testing has shown no reliability issues from either of these cosmetic differences.